

Maximum power dissipation (P_D) <u>1/</u> :	
Device types 01 and 02- - - - -	385 mW
Device type 03- - - - -	430 mW
Device type 04- - - - -	336 mW
Device type 05- - - - -	468 mW
Device type 06- - - - -	545 mW
Device type 07- - - - -	479 mW
Device type 08- - - - -	550 mW
Lead temperature (soldering, 10 seconds)-	300°C
Thermal resistance, junction-to-case (θ_{JC}):	
Cases E, F, 2, and X- - - - -	(See MIL-M-38510, appendix C)
Junction temperature (T_J) <u>2/</u> - - - - -	+175°C

1.4 Recommended operating conditions.

Supply voltage (V_{CC}) - - - - -	4.5 V dc minimum to 5.5 V dc maximum
Minimum high-level input voltage (V_{IH}) - -	2.0 V dc
Maximum low-level input voltage (V_{IL}) <u>3/</u> - -	0.8 V dc
Case operating temperature range (T_C) - -	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government documents.

2.1.1 Specification and standard. The following specification and standard form a part of this specification to the extent specified herein. Unless otherwise specified, the issues of these documents shall be those listed in the issue of the Department of Defense Index of Specifications and Standards and supplement thereto, cited in the solicitation.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by contractors in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this specification and the references cited herein (except for associated detail specifications, specification sheets or MS standards), the text of this specification shall take precedence. Nothing in this specification, however, shall supersede applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Detail specification. The individual item requirements shall be in accordance with MIL-M-38510, and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

1/ Must withstand the added P_D due to short circuit condition (e.g., I_{QS}) test.

2/ Maximum junction temperature shall not be exceeded except for allowable short duration burn-in screening conditions per method 5004 of MIL-STD-883.

3/ $V_{IL} = 0.7$ V at 125°C.

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions $-55^{\circ}\text{C} < T_C < +125^{\circ}\text{C}$ unless otherwise specified	Device type	Limits	Unit
				Min	Max
High-level output voltage	V_{OH}	$V_{CC} = 4.5 \text{ V}$; $V_{IL} = 0.8 \text{ V}$ $I_{OH} = -1.0 \text{ mA}$ $@T_C = 125^{\circ}\text{C}$, $V_{IL} = 0.7 \text{ V}$	01,02 03,04	2.5	V
		$V_{CC} = 4.5 \text{ V}$; $V_{IL} = 0.8 \text{ V}$ $I_{OH} = -2.0 \text{ mA}$ $@T_C = 125^{\circ}\text{C}$, $V_{IL} = 0.7 \text{ V}$	05,06	2.4	
		$V_{CC} = 4.5 \text{ V}$; $V_{IL} = 0.8 \text{ V}$ $I_{OH} = -1.0 \text{ mA}$ $@T_C = 125^{\circ}\text{C}$, $V_{IL} = 0.7 \text{ V}$	07,08		
Low-level output voltage	V_{OL}	$V_{CC} = 4.5 \text{ V}$ $I_{OL} = 20 \text{ mA}$	A11	.5	V
		$T_C = 125^{\circ}\text{C}$	A11	.45	V
Input clamp voltage	V_{IC}	$V_{CC} = 4.5 \text{ V}$ $I_{IN} = -18 \text{ mA}$, $T_C = 25^{\circ}\text{C}$	A11	-1.2	V
Off-state output current	I_{OFF1}	$V_{CC} = 5.5 \text{ V}$ $V_O = 2.7 \text{ V}$	05,06 07,08	50	μA
Off-state output current	I_{OFF2}	$V_{CC} = 5.5 \text{ V}$ $V_O = 0.5 \text{ V}$	05,06 07,08	-50	μA
High-level input current	I_{IH1}	$V_{CC} = 5.5 \text{ V}$ $V_{IN} = 2.7 \text{ V}$	A11 inputs	01,02 05,08	μA
			A and B inputs	03,04	
			A11 inputs except S	06,07	
			S and G inputs	03,04	
			S input	06,07	
High-level input current	I_{IH2}	$V_{CC} = 5.5 \text{ V}$ $V_{IN} = 5.5 \text{ V}$	A11 inputs	A11	1.0 mA
Low-level input current	I_{IL}	$V_{CC} = 5.5 \text{ V}$ $V_{IN} = 0.5 \text{ V}$	A11 inputs	01,02 05,08	mA
			A and B inputs	03,04	
			A11 inputs except S	06,07	
			S and G inputs	03,04	
			S input	06,07	

See footnote at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55^{\circ}\text{C} < T_C < +125^{\circ}\text{C}$ unless otherwise specified	Device type	Limits	Unit
				Min	Max
Short circuit output current	I _{OS}	V _{CC} = 5.5 V 1/	A11	-40	-110 mA
Supply current	I _{CC}	V _{CC} = 5.5 V	01,02	70	mA
			03	78	
			04	61	
Supply current	I _{CC0}	V _{CC} = 5.5 V V _{IN} = 5.5 V	05	85	mA
			06	99	
			07	87	
			08	100	
Supply current	I _{CC1}	V _{CC} = 5.5 V	08	80	mA
Collector cut-off current	I _{CEx}	V _{CC} = 5.5 V, V _{OH} = 5.5 V V _{IL} = GND, V _{IH} = 5.5 V	01 thru 08	250	μA
Low-level supply current	I _{CCL}	V _{CC} = 5.5 V	06	93	mA
			07	81	
High-level supply current	I _{CCH}	V _{CC} = 5.5 V	06	68	mA
			07	56	
From A, B, C, to Y	t _{TPLH2}	V _{CC} = 5.0 V C _L = 50 pF R _L = 280Ω	01	2.0	26.0 ns
From A, B, C, to Y	t _{TPHL2}		01	2.0	26.0 ns
From A, B, C, to W	t _{TPLH1}		01	2.0	22.0 ns
From A, B, C, to W	t _{TPHL1}		01	2.0	20.0 ns
From any D to Y	t _{TPLH6}		01	2.0	18.0 ns
From any D to Y	t _{TPHL6}		01	2.0	18.0 ns
From any D to W	t _{TPLH5}		01	2.0	11.5 ns

See footnote at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T _C < +125°C unless otherwise specified	Device type	Limits		Unit
				Min	Max	
From any D to W	tPHL5	V _{CC} = 5.0 V C _L = 50 pF R _L = 280Ω	01	2.0	11.5	ns
From strobe to Y	tPLH4		01	2.0	24.0	ns
From strobe to Y	tPHL4		01	2.0	26.0	ns
From strobe to W	tPLH3		01	2.0	19.5	ns
From strobe to W	tPHL3		01	2.0	18.0	ns
From data to Y	tPLH1		02,08	2.0	14.5	ns
From data to Y	tPHL1		02,08	2.0	14.5	ns
From select to Y	tPLH2		02,08	2.0	26.0	ns
From select to Y	tPHL2		02,08	2.0	26.0	ns
From strobe to Y	tPLH3		02	2.0	22.0	ns
From strobe to Y	tPHL3		02	2.0	21.0	ns
From data to Y	tPLH2		03	2.0	12.0	ns
			04		11.0	
From data to Y	tPHL2		03	2.0	12.0	ns
			04		11.0	
From strobe to Y	tPLH3		03	2.0	18.0	ns
			04		18.0	
From strobe to Y	tPHL3		03	2.0	18.5	ns
			04		18.5	

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T _C < +125°C unless otherwise specified	Device type	Limits		Unit
				Min	Max	
From select to Y	tPLH1	V _{CC} = 5.0 V C _L = 50 pF R _L = 280Ω	03	2.0	18.5	ns
			04		18.5	
From select to Y	tPHL1		03	2.0	18.5	ns
			04		18.5	
From A, B, C to Y	tPLH2		05	2.0	26.0	ns
From A, B, C to Y	tPHL2		05	2.0	28.0	ns
From A, B, C to W	tPLH1		05	2.0	22.0	ns
From A, B, C to W	tPHL1		05	2.0	20.0	ns
From any D to Y	tPLH4		05	2.0	18.0	ns
From any D to Y	tPHL4		05	2.0	18.0	ns
From any D to W	tPLH3		05	2.0	11.5	ns
From any D to W	tPHL3		05	2.0	11.5	ns
From strobe to Y	tZH3		05	2.0	25.5	ns
From strobe to Y	tZL3		05	2.0	27.5	ns
From strobe to Y	tHZ4		05	2.0	24.0	ns
From strobe to Y	tLZ4		05	2.0	22.0	ns
From strobe to W	tZH1		05	2.0	25.5	ns
From strobe to W	tZL1		05	2.0	27.5	ns
From strobe to W	tHZ2		05	2.0	24.0	ns

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T _C < +125°C unless otherwise specified	Device type	Limits		Unit
				Min	Max	
From strobe to W	t _{LZ2}	V _{CC} = 5.0 V C _L = 50 pF R _L = 280Ω	05	2.0	22.0	ns
From select to Y	t _{PLH1}		06	2.0	22.0	ns
			07		18.5	
			06	2.0	22.0	ns
From select to Y	t _{PHL1}		07		18.5	
			06	2.0	12.0	ns
			07		10.0	
From data to Y	t _{PLH2}		06	2.0	11.0	ns
			07		10.0	
			05,06	2.0	28.0	ns
From output control to Y	t _{ZH}		07		28.0	
			08		30.0	
			05,06	2.0	30.0	ns
From output control to Y	t _{ZL}		07		30.0	
			08		31.0	
			05,06	2.0	24.0	ns
From output control to Y	t _{HZ}		07		24.0	
			08		18.0	
			05,06	2.0	22.0	ns
From output control to Y	t _{LZ}		07		22.0	
			08		20.0	

1/ Not more than one output should be shorted at one time.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth tables. The truth tables shall be as specified on figure 2.

3.2.3 Schematic circuits. Schematic circuits shall be submitted to the preparing activity prior to inclusion of a manufacturer's device in the specification and shall be submitted to the qualifying activity and agent activity (DESC-ECS) as a prerequisite for qualification. All qualified manufacturers' schematics shall be maintained by the agent activity and will be available upon request.

3.3 Lead material and finish. The lead material and finish shall be in accordance with MIL-M-38510 (see 6.4).

3.4 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I, and apply over the full recommended case operating temperature range.

3.5 Electrical test requirements. The electrical test requirements for each device class shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table III.

3.6 Marking. Marking shall be in accordance with MIL-M-38510 and 1.2 herein.

3.7 Microcircuit group assignment. The devices covered by this specification shall be in microcircuit group number 11 (see MIL-M-38510, appendix E).

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (see table III)	
	Class S devices	Class B devices
Interim electrical parameters (method 5004)	1	1
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 9, 10, 11	1*, 2, 3, 7, 9
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10, 11	1, 2, 3, 7, 8, 9, 10, 11
Group B test requirements (method 5005) subgroup 5	1, 2, 3, 7, 8, 9, 10, 11	N/A
Group C end-point electrical parameters (method 5005)	N/A	1, 2, 3
Group D end-point electrical parameters (method 5005)	1, 2, 3	1, 2, 3

* PDA applies to subgroup 1 (see 4.2c).

Pin number Case	Pin name		Pin name		Pin name		Pin name		Pin name		Pin name		Pin name	
	Device type 01 Device type 02 Device type 03 Device type 04 Device type 05 Device type 06 Device type 07 Device type 08													
2, X	E, F	2, X	E, F	2, X	E, F	2, X	E, F	2, X	E, F	2, X	E, F	2, X	E, F	2, X
1	NC	D3	NC	1G	NC	S	NC	S	NC	D3	NC	S	NC	S
2	NC	D3	1G	B	S	1A	1A	1B	1B	D2	1A	1A	1B	1G
3	NC	D2	D1	B	1A	1A	1B	1Y	1Y	D2	1A	1B	1B	B
4	NC	D1	D0	1C3	1C2	1B	1Y	1B	1Y	D1	1B	1Y	1B	1C3
5	NC	D0	Y	1C3	1C2	1C1	1Y	2A	2A	D0	1B	1Y	1B	1C2
6	NC	W	NC	1C2	1C1	1C0	1Y	2B	2B	Y	1Y	2A	1Y	1G
7	NC	ST	ST	1C1	1C0	1C0	1Y	2A	2Y	NC	NC	2B	NC	1G
8	Y	W	GND	1C0	1C0	1Y	2Y	2B	2Y	ST	2A	2Y	2A	NC
9	ST	W	GND	1Y	2Y	2Y	2Y	GND	W	W	2B	GND	1C1	1Y
10	10	3ND	B	GND	2C0	GND	3Y	2Y	3Y	ST	C	2Y	3Y	1Y
11	11	NC	A	NC	2C0	GND	3B	GND	GND	3B	GND	3B	GND	2Y
12	12	C	D7	2Y	2C1	NC	3A	NC	NC	A	NC	3A	NC	2Y
13	13	B	D6	2C2	2C2	3Y	4Y	3Y	4Y	C	D7	3Y	4Y	2Y
14	14	A	D5	2C0	2C3	3B	4B	3B	4B	B	D6	3B	4B	2C2
15	15	D7	D4	2C1	A	3A	4A	3A	4A	A	D5	3A	4A	2C3
16	16	NC	VCC	2C2	2G	4Y	G	4Y	G	D7	D4	4Y	OE	2C1
17	17	D6	VCC	VCC	NC	VCC								
18	18	D5	A	2C3	4B	4A	4A	4B	4B	D6	4B	4A	4B	2C3
19	19	D4	2G	A	2G	4A	4A	4A	4A	D5	4D	4A	4A	A
20	20	VCC	VCC	2G										

FIGURE 1. Terminal connections.

Device types 01 and 05

Inputs			Outputs	
Select	Strobe	Data	Type 01	Type 05
C B A	S	D0 D1 D2 D3 D4 D5 D6 D7	Y W Y W	
X X X	H	X X X X X X X X	L H Z Z	
L L L	L	L X X X X X X X	L H L H	
L L L	L	H X X X X X X X	H L H L	
L L H	L	X L X X X X X X	L H L H	
L L H	L	X H X X X X X X	H L H L	
L H L	L	X X L X X X X X	L H L H	
L H L	L	X X H X X X X X	H L H L	
L H H	L	X X X L X X X X	L H L H	
L H H	L	X X X H X X X X	H L H L	
H L L	L	X X X X L X X X	L H L H	
H L L	L	X X X X H X X X	H L H L	
H L H	L	X X X X X L X X	L H L H	
H L H	L	X X X X X H X X	H L H L	
H H L	L	X X X X X X L X	L H L H	
H H L	L	X X X X X X H X	H L H L	
H H H	L	X X X X X X X L	L H L H	
H H H	L	X X X X X X X H	H L H L	

H = high logic level
L = low logic level

Z = high impedance
X = irrelevant

FIGURE 2. Truth tables.

Device type 02

Select inputs	Data inputs				Strobe	Output	
B	A	C0	C1	C2	C3	G	Y
X	X	X	X	X	X	H	L
L	L	L	X	X	X	L	L
L	L	H	X	X	X	L	H
L	H	X	L	X	X	L	L
L	H	X	H	X	X	L	H
H	L	X	X	L	X	L	L
H	L	X	X	H	X	L	H
H	H	X	X	X	L	L	L
H	H	X	X	X	H	L	H

Address inputs A and B are common to both sections.
H = high level, L = low level, X = irrelevant.

Device types 03 and 04

Inputs			Output Y	
Strobe	Select	A B	Type 03	Type 04
H	X	X X	L	H
L	L	L X	L	H
L	L	H X	H	L
L	H	X L	L	H
L	H	X H	H	L

H = high level, L = low level, X = irrelevant.

FIGURE 2. Truth tables - Continued.

Device types 06 and 07

Function table

Inputs			Output Y	
Output control	Select	A B	Type 06	Type 07
H	X	X X	Z	Z
L	L	L X	L	H
L	L	H X	H	L
L	H	X L	L	H
L	H	X H	H	L

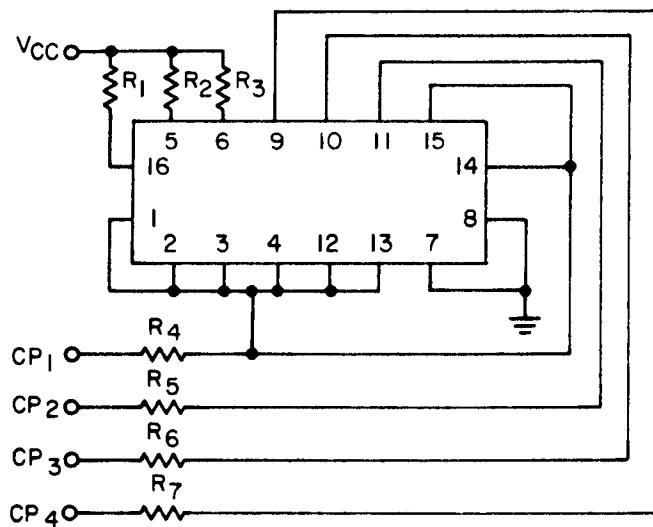
H = high level, L = low level, X = irrelevant,
Z = high impedance (off).

Device type 08

Select inputs	Data inputs				Output control	Output
B A	C0	C1	C2	C3	G	Y
X X	X	X X	X X	X	H	Z
L L	L	X X	X X	X	L	L
L L	H	X X	X X	X	L	H
L H	X	L X	X X	X	L	L
L H	X	H X	X X	X	L	H
H L	X X	L X	X X	X	L	L
H L	X X	H X	X X	X	L	H
H H	X X	X L	X X	X	L	L
H H	X X	X H	X X	X	L	H

Address inputs A and B are common to both sections.
H = high level, L = low level, X = irrelevant,
Z = high impedance (off).

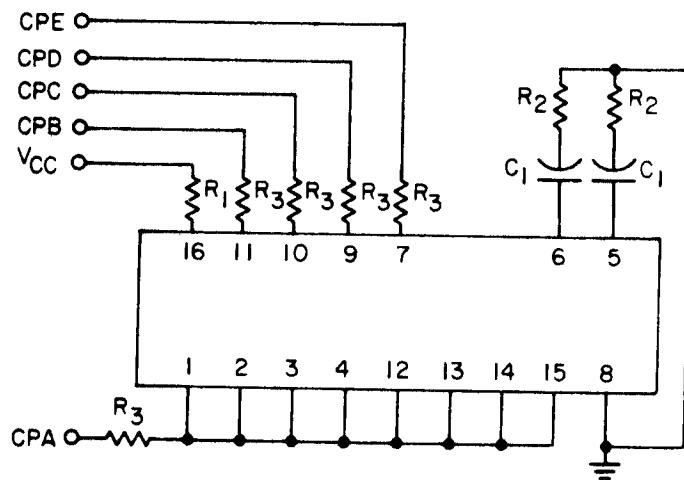
FIGURE 2. Truth tables - Continued.

Device types 01 and 05

NOTES:

1. $R_2, R_3 = 220\Omega \pm 5\%$.
 R_4 through $R_7 = 27\Omega \pm 5\%$.
2. $CP_1 = 100 \text{ kHz} \pm 50\%$; $CP_2 = 50 \text{ kHz} \pm 50\%$;
 $CP_3 = 25 \text{ kHz} \pm 50\%$; $CP_4 = 12.5 \text{ kHz} \pm 50\%$;
square wave; duty cycle = $50 \pm 15\%$; $V_{IL} = -0.5 \text{ V}$
minimum to 0.8 V maximum; $V_{IH} = 2.0 \text{ V}$ minimum to
 5.5 V maximum.
3. V_{CC} and R_1 shall be chosen to insure 5.0 V minimum
is present at device V_{CC} terminal.

FIGURE 3. Burn-in and life test circuits.

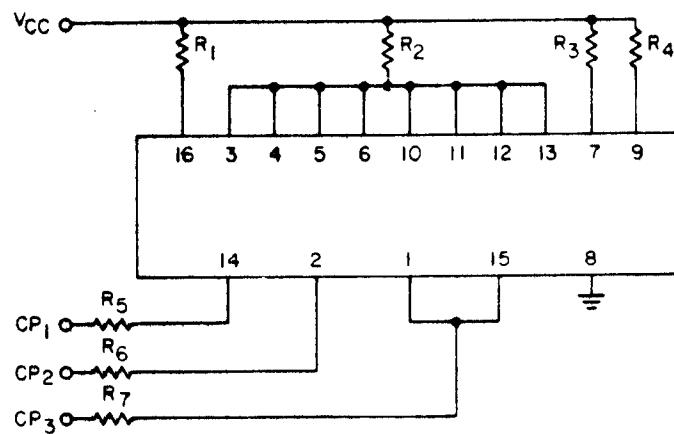
Device types 01 and 05 - Alternate circuit.

NOTES:

1. $R_2 = 75\Omega \pm 5\%$.
 $R_3 = 27\Omega \pm 5\%$.
2. $C_1 = .047 \mu F$.
3. CPA = 100 kHz $\pm 50\%$; CPB = 50 kHz $\pm 50\%$;
CPC = 25 kHz $\pm 50\%$; CPD = 12.5 kHz $\pm 50\%$;
CPE = 6.25 $\pm 50\%$; square waves; duty cycle = 50 $\pm 15\%$;
 $V_{IL} = -0.5 V$ minimum to 0.8 V maximum; $V_{IH} = 2.0 V$
minimum to 5.5 V maximum.
4. V_{CC} and R_1 shall be chosen to insure a 5.0 V minimum is present
at the device V_{CC} terminal.

FIGURE 3. Burn-in and life test circuits - Continued.

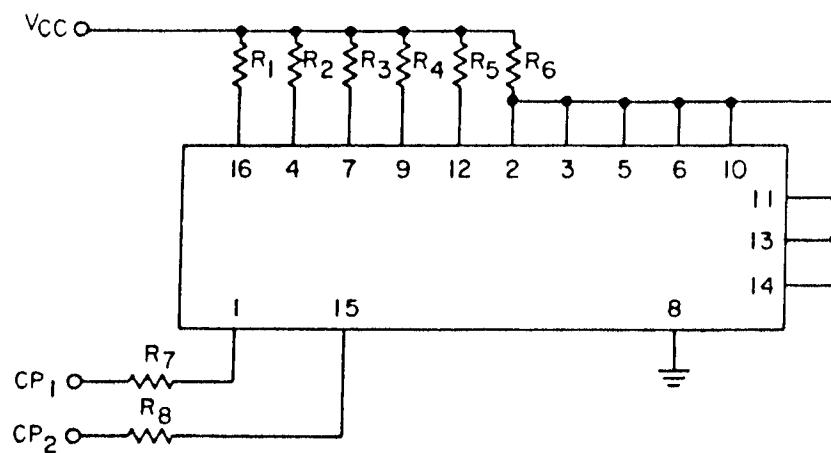
Device type 02



NOTES:

1. $R_2 = R_3 = R_4 = 220\Omega \pm 5\%$.
 $R_5 = R_6 = R_7 = 27\Omega \pm 5\%$.
2. $CP_1 = 100 \text{ kHz} \pm 50\%$; $CP_2 = 50 \text{ kHz} \pm 50\%$; $CP_3 = 25 \text{ kHz} \pm 50\%$; square waves; duty cycle = $50 \pm 15\%$; $V_{IL} = -0.5 \text{ V}$ minimum to 0.8 V maximum; $V_{IH} = 2.0 \text{ V}$ minimum to 5.5 V maximum.
3. V_{CC} and R_1 shall be chosen to insure a 5.0 V minimum at the device V_{CC} terminal.

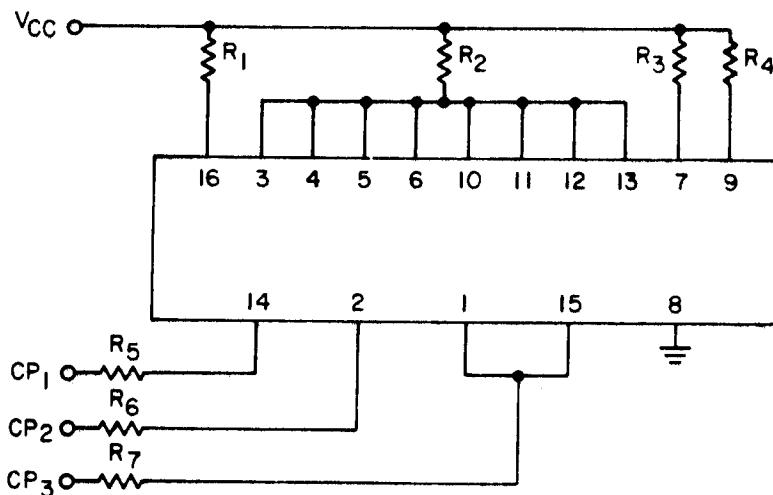
FIGURE 3. Burn-in and life test circuits - Continued.

Device types 03, 04, 06 and 07

NOTES:

1. R₂ through R₆ = 270Ω ±5%.
2. R₇ and R₈ = 27Ω ±5%.
3. CP₁ = 100 kHz ±50%; CP₂ = 50 kHz ±50%; square waves; duty cycle = 50 ±15%; V_{IL} = -0.5 V minimum to 0.8 V maximum; V_{IH} = 2.0 V minimum to 5.5 V maximum.
4. V_{CC} and R₁ shall be chosen to insure a 5.0 V minimum at the device V_{CC} terminal.

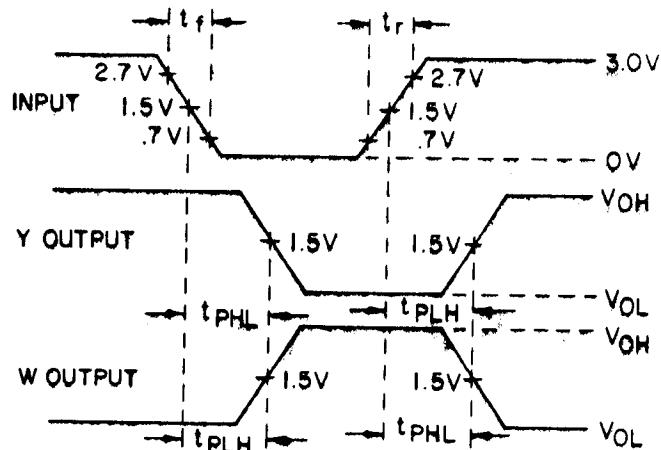
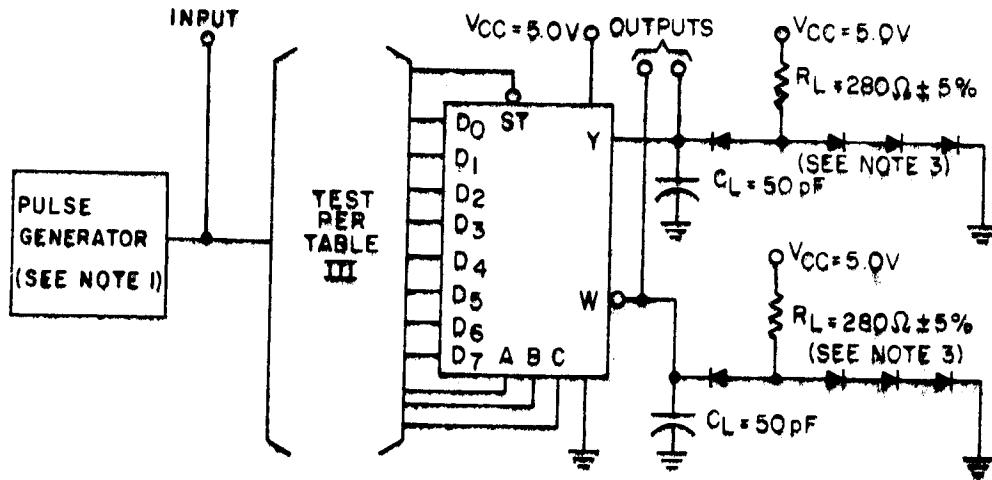
FIGURE 3. Burn-in and life test circuits - Continued.

Device type 08

NOTES:

1. $R_2 = R_3 = R_4 = 220\Omega \pm 5\%$.
 $R_5 = R_6 = R_7 = 27\Omega \pm 5\%$.
2. $CP_1 = 100 \text{ kHz} \pm 50\%$; $CP_2 = 50 \text{ kHz} \pm 50\%$; $CP_3 = 25 \text{ kHz} \pm 50\%$; square waves; duty cycle = $50 \pm 15\%$; $V_{IL} = -0.5 \text{ V}$ minimum to 0.8 V maximum; $V_{IH} = 2.0 \text{ V}$ minimum to 5.5 V maximum.
3. V_{CC} and R_1 shall be chosen to insure a 5.0 V minimum is present at the device V_{CC} terminal.

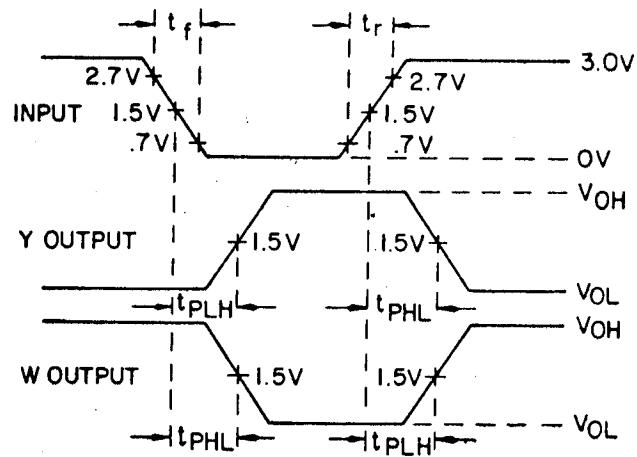
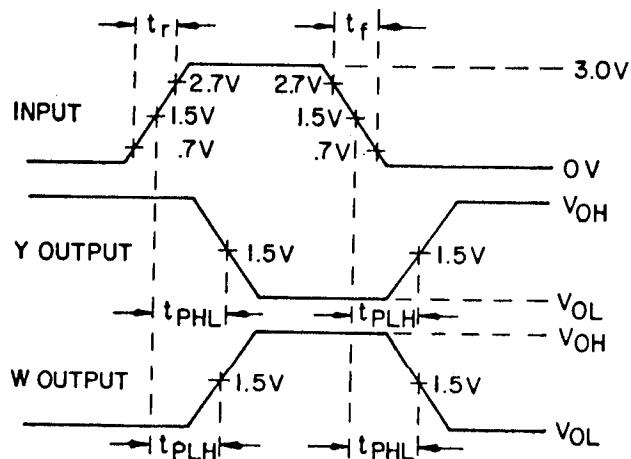
FIGURE 3. Burn-in and life test circuits - Continued.

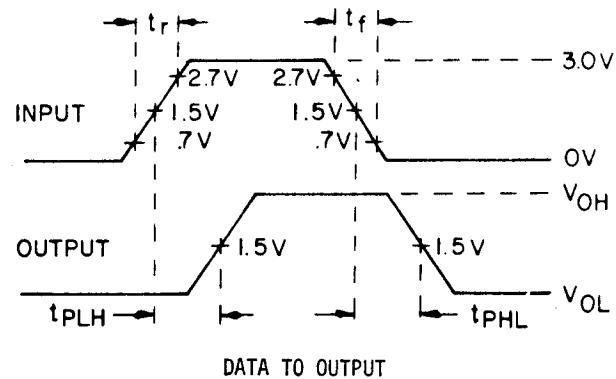
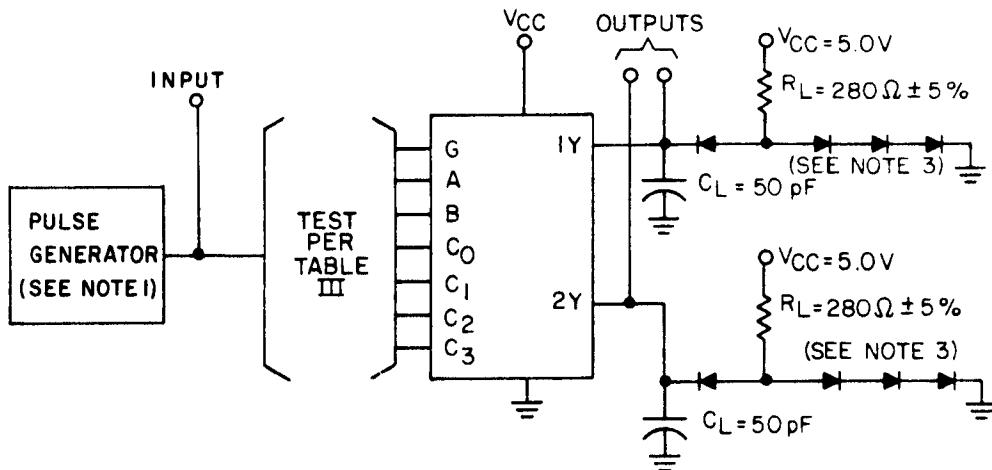


NOTES:

1. The input pulse has the following characteristics: $t_r = t_f \leq 2.5\text{ ns}$, $\text{PRR} \leq 1\text{ MHz}$, and $Z_{OUT} \approx 50\Omega$.
2. C_L includes probe and jig capacitance.
3. All diodes are 1N3064 or equivalent.
4. Only the output under test needs to be loaded.

FIGURE 4. Switching time test circuits and waveforms for device type 01.

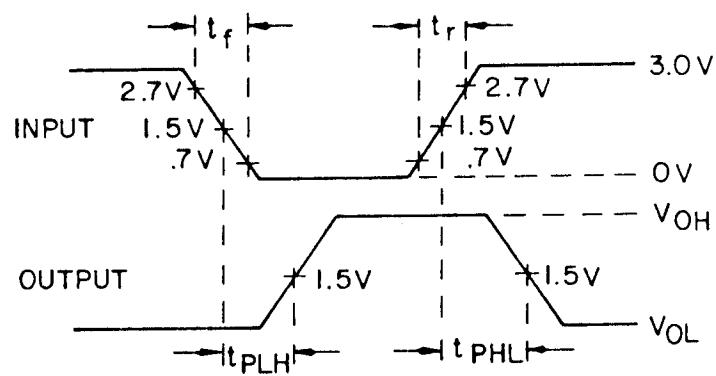
Strobe to output voltage waveforms - type 01.Data to output voltage waveforms - type 01.FIGURE 4. Switching time test circuits and waveforms for device type 01 - Continued.



NOTES:

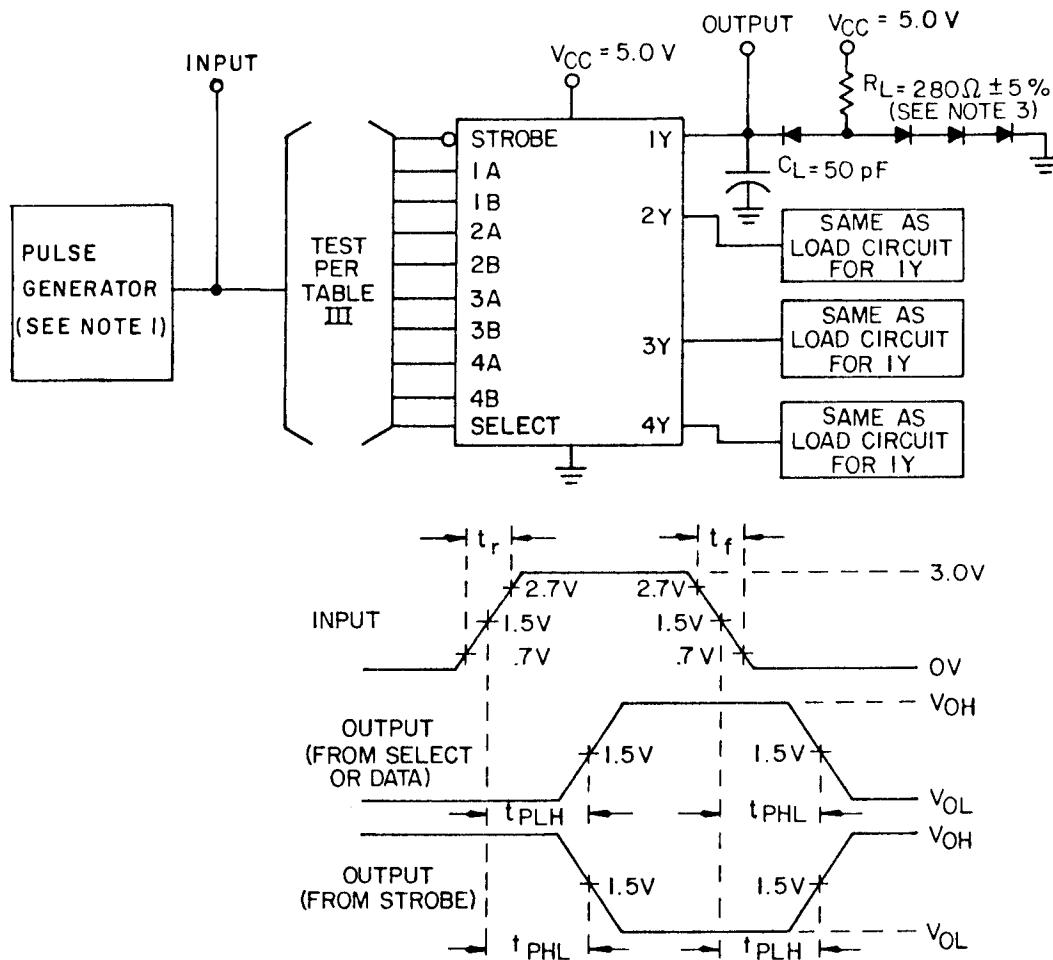
1. The input pulse has the following characteristics: $t_r = t_f \leq 2.5$ ns, PRR ≤ 1 MHz, and $Z_{OUT} \approx 50\Omega$.
2. C_L includes probe and jig capacitance.
3. All diodes are 1N3064 or equivalent.
4. Only the output under test needs to be loaded.

FIGURE 5. Switching time test circuits and waveforms for device type 02.



Select and strobe to output voltage waveforms - type 02.

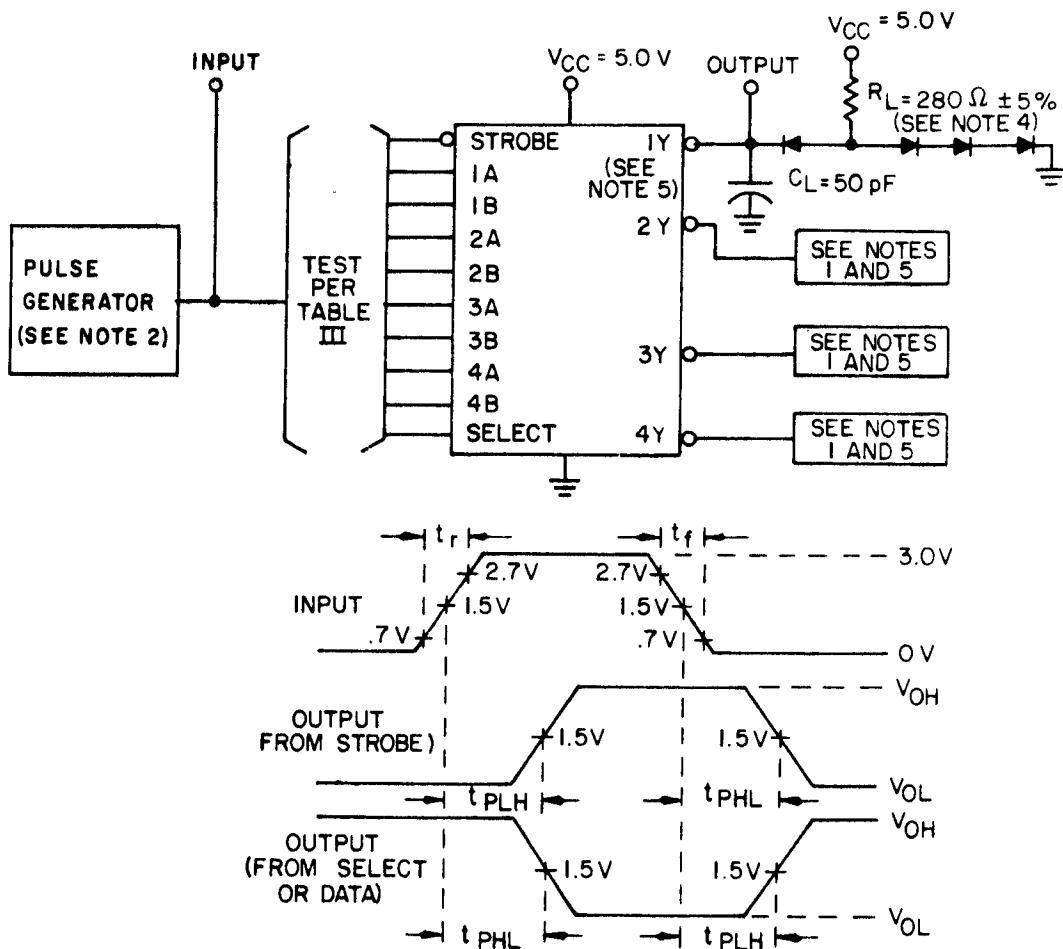
FIGURE 5. Switching time test circuits and waveforms for device type 02 - Continued.



NOTES:

1. The input pulse has the following characteristics: PRR $\leq 1\text{ MHz}$, $t_r = t_f \leq 2.5\text{ ns}$, $Z_{OUT} \approx 50\Omega$.
2. C_L includes probe and jig capacitance.
3. All diodes are 1N3064 or equivalent.
4. Load circuit is required on a given output only where table III indicates "OUT" on that output. Load circuits may otherwise be omitted.

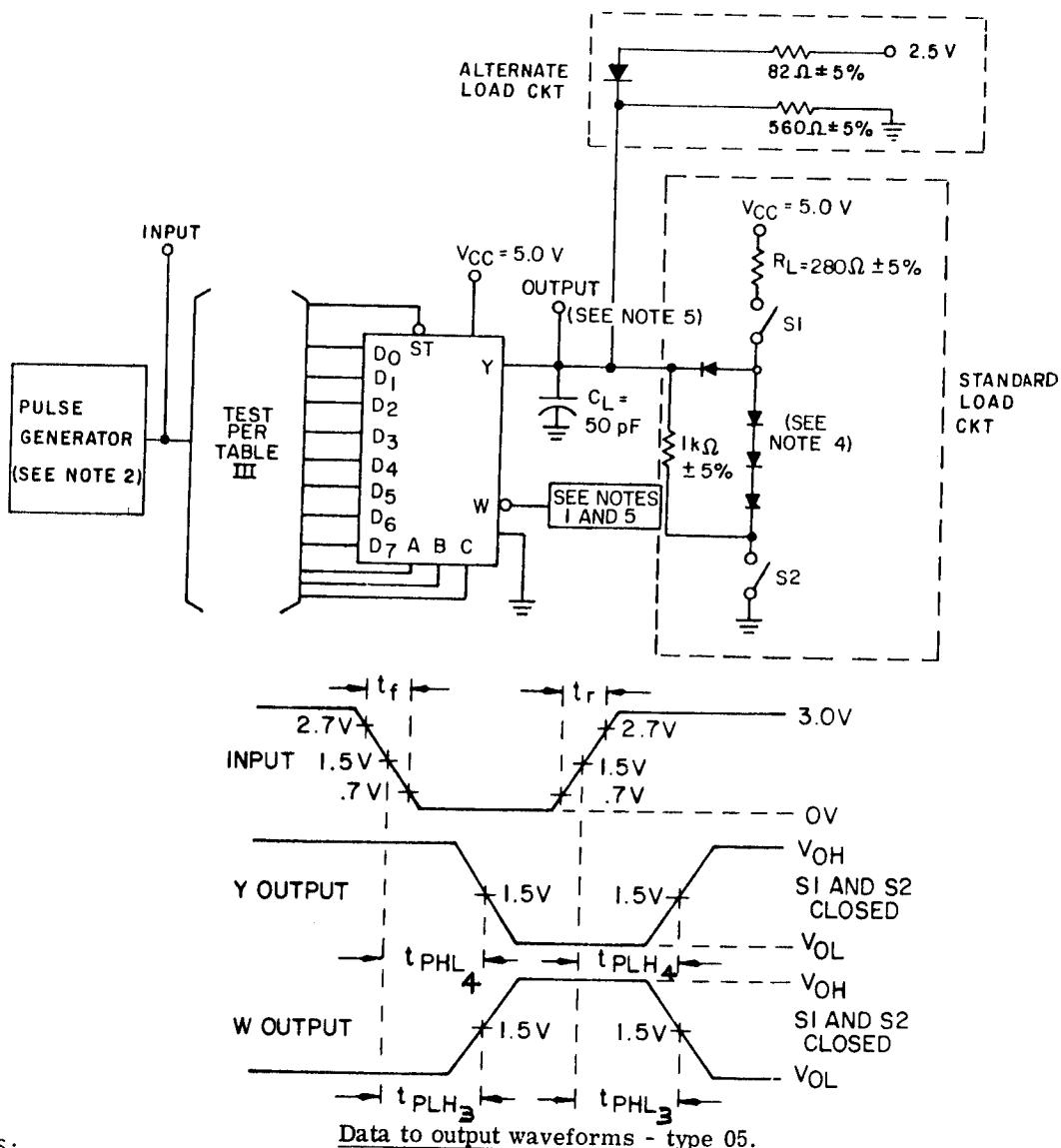
FIGURE 6. Switching time test circuits and waveforms for device type 03.



NOTES:

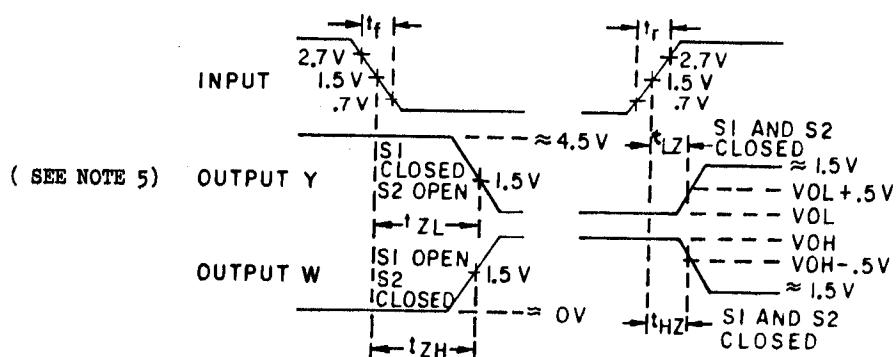
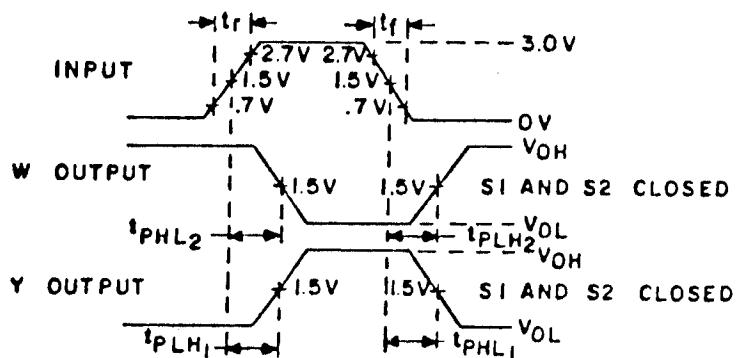
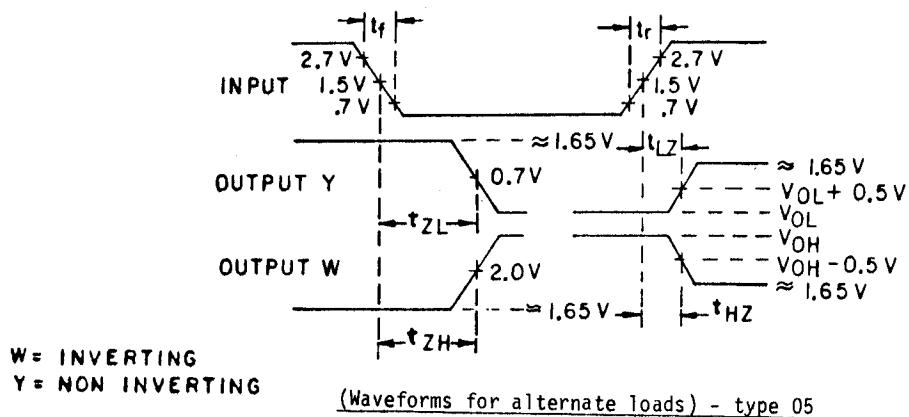
1. Connect same load as shown for output 1Y.
2. The input pulse has the following characteristics: PRR \leq 1 MHz, $t_r = t_f \leq 2.5$ ns, Z_{OUT} \approx 50Ω.
3. C_L includes probe and jig capacitance.
4. All diodes are 1N3064 or equivalent.
5. Load circuit is required on a given output only where table III indicates "OUT" on that output. Load circuits may otherwise be omitted.

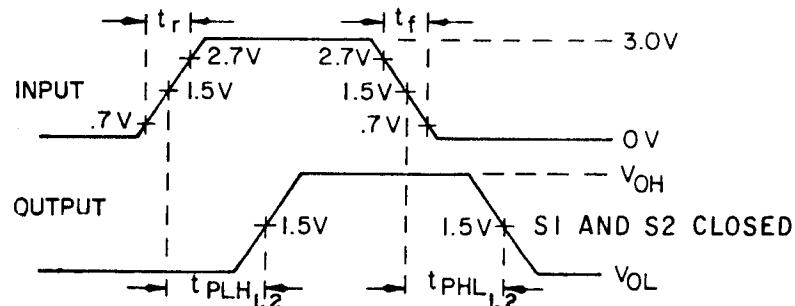
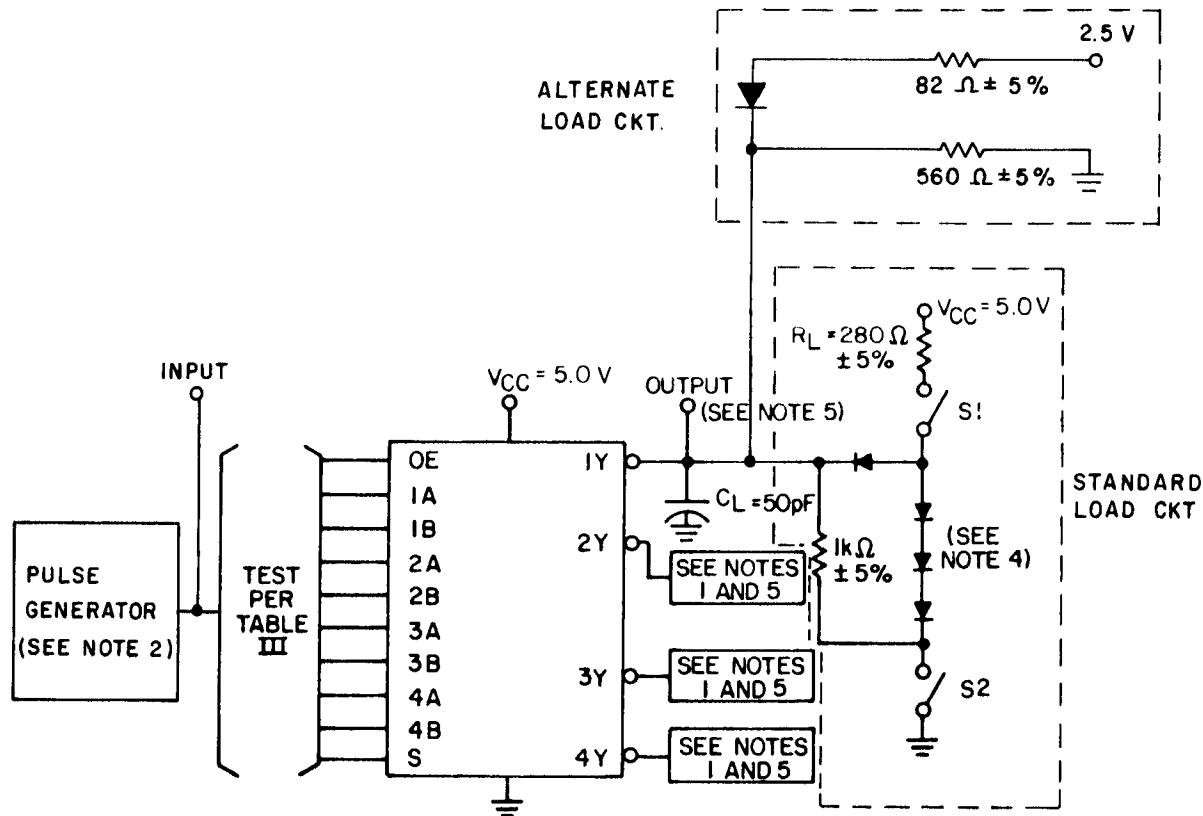
FIGURE 7. Switching time test circuits and waveforms for device type 04.

**NOTES:**

1. Connect same load as shown for Y output.
2. The input pulse has the following characteristics: $t_r = t_f \leq 2.5$ ns, PRR ≤ 1 MHz and $Z_{out} \approx 50\Omega$.
3. C_L includes probe and jig capacitance.
4. All diodes are 1N3064 or equivalent.
5. Load circuit is required on a given output only where table III indicates "OUT" on that output. Load circuits may otherwise be omitted.
 - A. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 - B. Output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
6. Manufacturer may test with either the standard load circuit or the alternate load circuit at his option.

FIGURE 8. Switching time test circuits and waveforms for device type 05.

FIGURE 8. Switching time test circuits and waveforms for device type 05 - Continued.

**NOTES:**

1. Connect same load as shown for **IY** output.
2. The input pulse has the following characteristics: $t_r = t_f \leq 2.5$ ns, PRR ≤ 1 MHz, and $Z_{OUT} \approx 50\Omega$.
3. C_L includes probe and jig capacitance.
4. All diodes are 1N3064 or equivalent.
5. Load circuit is required on a given output only where table III indicates "OUT" on that output. Load circuits may otherwise be omitted.
 - A. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 - B. Output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
6. Manufacturer may test with either the standard load circuit or the alternate load circuit at his option.

FIGURE 9. Switching time test circuits and waveforms for device type 06.

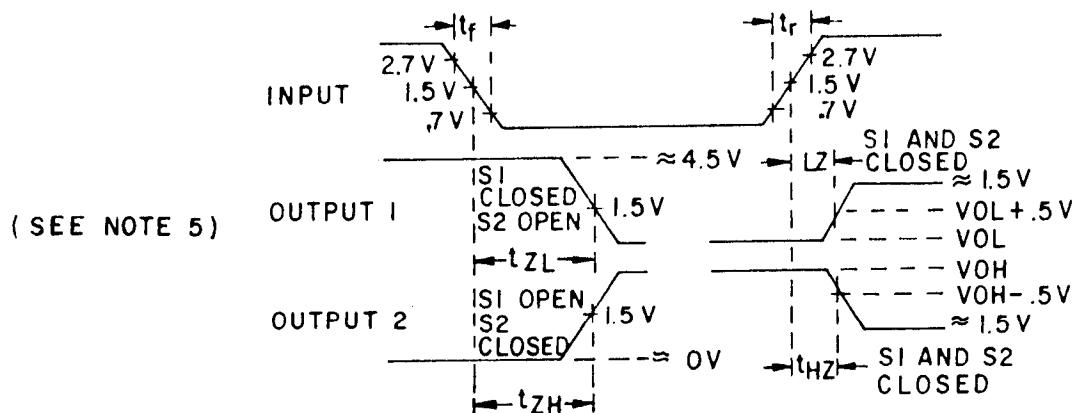
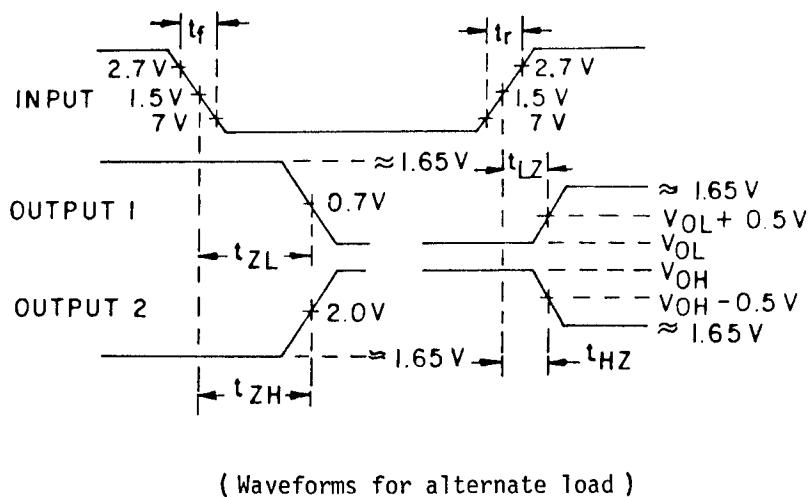
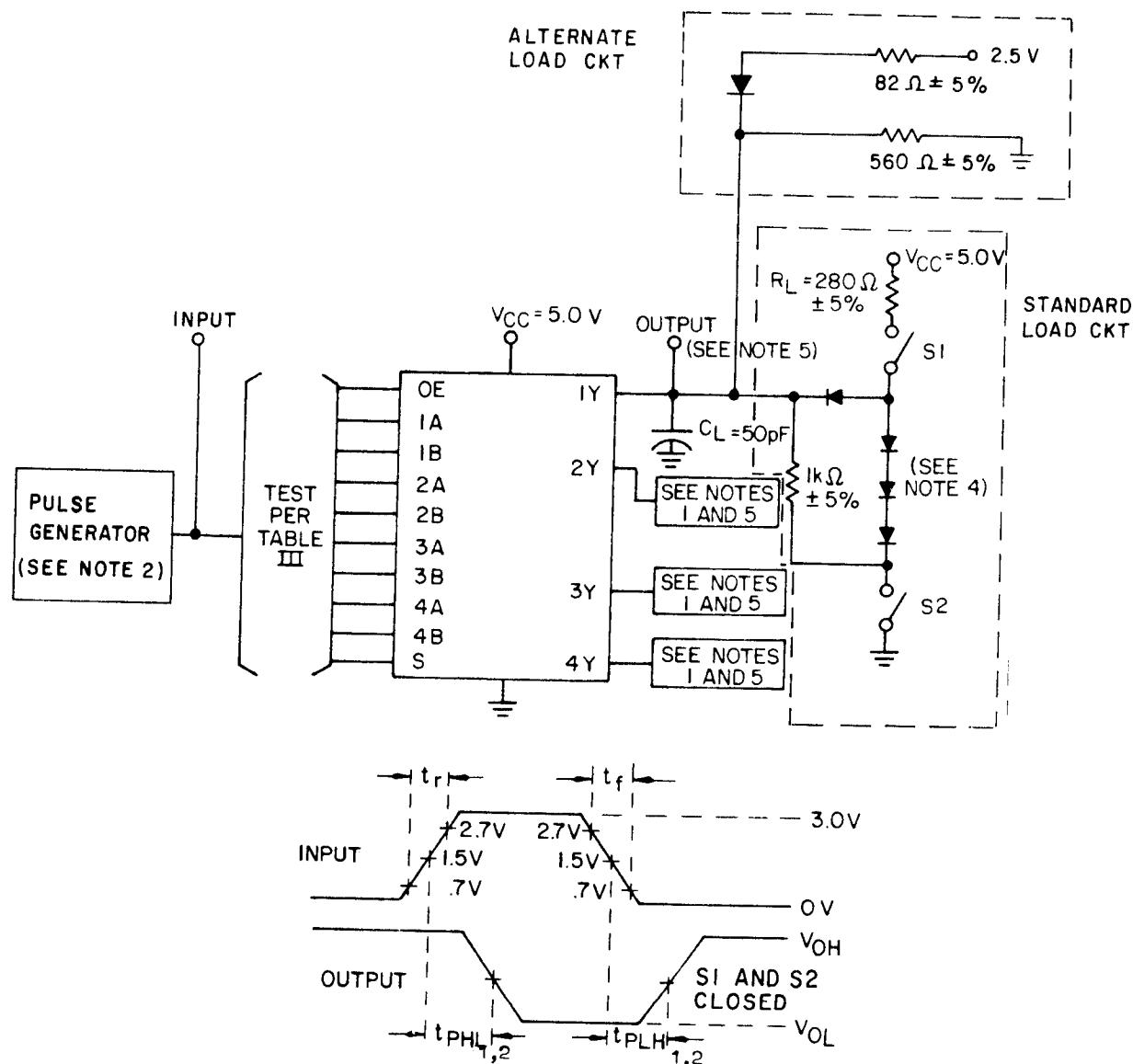


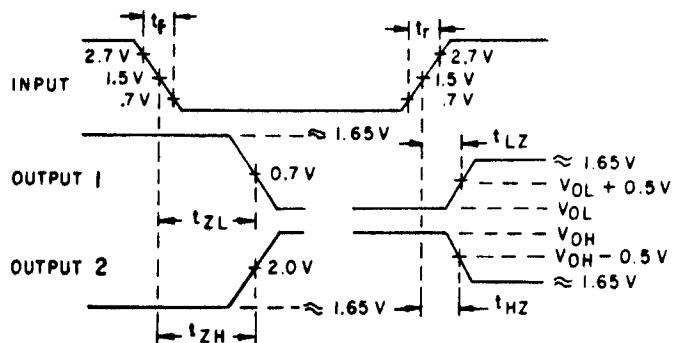
FIGURE 9. Switching time test circuits and waveforms for device type 06 - Continued.



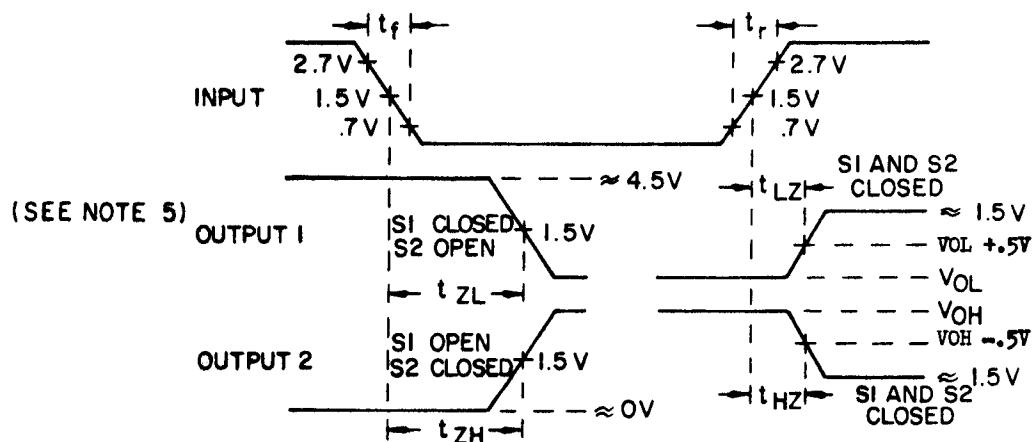
NOTES:

1. Connect same load as shown for 1Y output.
2. The input pulse has the following characteristics: $t_r = t_f \leq 2.5\text{ ns}$, $\text{PRR} \leq 1\text{ MHz}$ and $Z_{OUT} = 50\Omega$.
3. C_L includes probe and jig capacitance.
4. All diodes are 1N3064 or equivalent.
5. Load circuit is required on a given output only where table III indicates OUT on that output. Load circuits may otherwise be omitted.
 - A. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 - B. Output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
6. Manufacturer may test with either the standard load circuit or the alternate load circuit at his option.

FIGURE 10. Switching time test circuits and waveforms for device type 07.

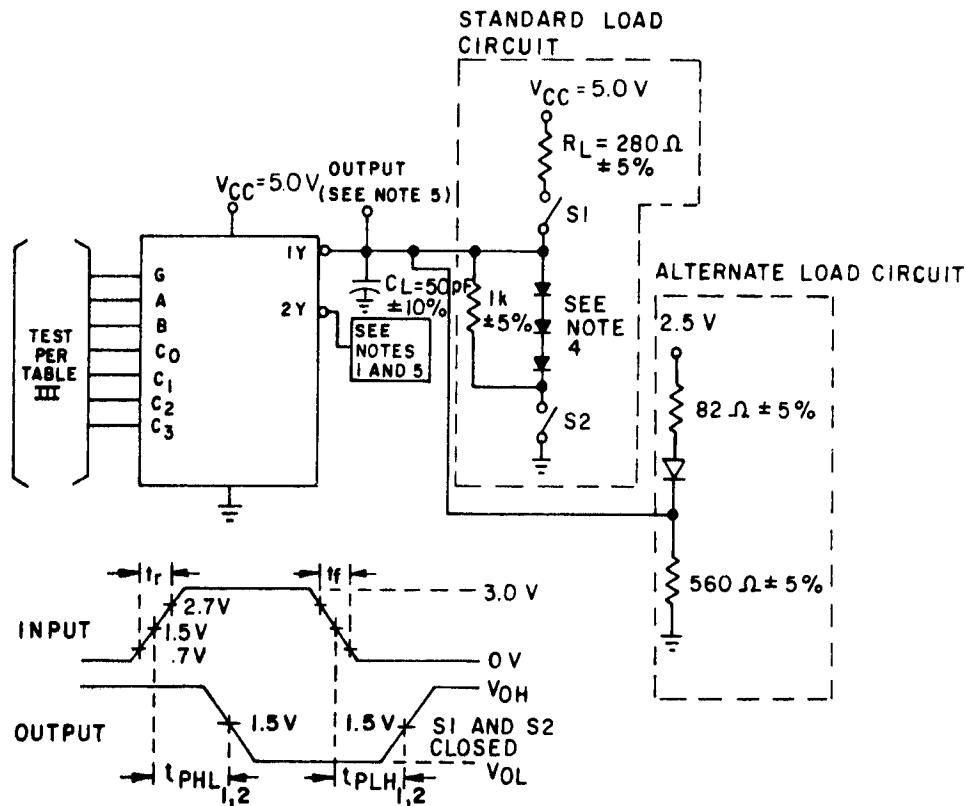


(Waveforms for alternate load)



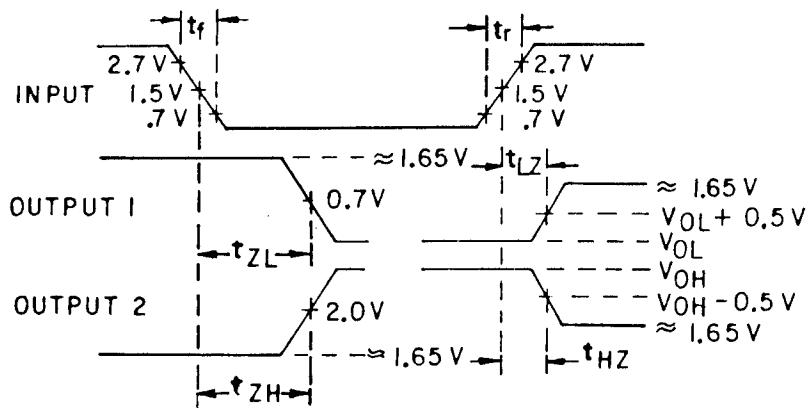
(Waveforms for standard load)

FIGURE 10. Switching time test circuits and waveforms for device type 07 - Continued.

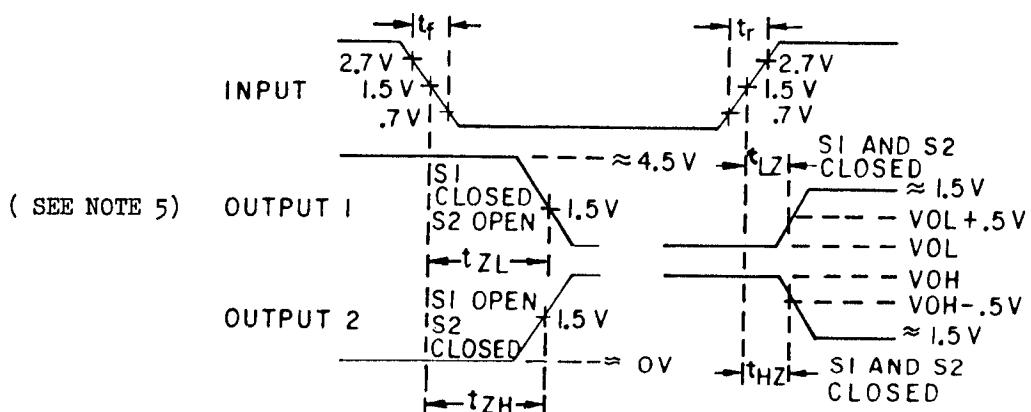
**NOTES:**

1. Connect same load as shown for 1Y output.
2. The input pulse has the following characteristics: $t_r = t_f \leq 2.5\text{ ns}$, $PRR \leq 1\text{ MHz}$, and $Z_{OUT} \approx 50\Omega$.
3. C_L includes probe and jig capacitance.
4. All diodes are 1N3064 or equivalent.
5. Load circuit is required on a given output only where table III indicates "OUT" on that output. Load circuits may otherwise be omitted.
 - A. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 - B. Output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
6. Manufacturer may test with either the standard load circuit or the alternate load circuit at his option.

FIGURE 11. Switching time test circuits and waveforms for device type 08.



(Waveforms for alternate load)



(Waveforms for standard load)

FIGURE 11. Switching time test circuits and waveforms for device type 08 - Continued.

TABLE III. Group A inspection for device type 31 - Continued
Terminal conditions (PTMS not designated may be H \geq 2.0 V, or L \leq 0.8 V, or open)

Subgroup	Symbol	MIL-STD-883 method	Bases H,F, Y,2,5/		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Test limits							
			no.	Test	J3	J2	J1	J0	Y	A	JT	GND	C	3	A	J7	J6	J5	J4	VCC	terminal	Min	Max	Unit				
$T_C = +25^\circ C$	tP1H5	3003 (F13,5)	100	99	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	5.0 V	"	2.0	9.0	ns				
		"	101	102	IN	"	"	"	"	"																		
		"	103	104	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"				
		"	105	106	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"				
	tP1L6	"	107	108	109	110	111	112	113	114	115	116	117	118	119	120	121	122	123	124	125	126	127	128				
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"				
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"				
	tP1R6	"	115	116	117	118	119	120	121	122	123	124	125	126	127	128	129	130	131	132	133	134	135	136	137			
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
$T_C = +125^\circ C$	tP1H1	"	123	124	125	126	127	128	129	120	121	122	123	124	125	126	127	128	129	120	121	122	123	124	125			
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
	tP1L4	"	126	127	128	129	120	121	122	123	124	125	126	127	128	129	120	121	122	123	124	125	126	127	128	129		
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
	tP1R2	"	129	130	131	127	128	129	120	121	122	123	124	125	126	127	128	129	120	121	122	123	124	125	126	127		
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
	tP1L2	"	132	133	134	135	136	137	138	139	130	131	132	133	134	135	136	137	138	139	130	131	132	133	134	135	136	
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
	tP1H3	"	136	137	138	139	130	131	132	133	134	135	136	137	138	139	130	131	132	133	134	135	136	137	138	139		
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"			
	tP1L4	"	138	139	130	131	132	133	134	135	136	137	138	139	130	131	132	133	134	135	136	137	138	139	130	131	132	
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"		
	tP1R4	"	139	130	131	132	133	134	135	136	137	138	139	130	131	132	133	134	135	136	137	138	139	130	131	132	133	134
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"		

See footnotes at end of device type 31.

TABLE III. Group A inspection for devi-
0.1 - Continued, or
0.1 - Continuity
or L < 0.8 V, or open)

Subgroup	Symbol	MIL- STD-883 method	Cases IEF, X257	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Measured terminal	Test limits	
		Test no.	D3	D2	D1	DO	Y	W	ST	GND	C	B	A	D7	D6	D5	D4	VCC	Min	Max	Unit	
10	TpHL5	Fig. 5	3003	139														5.0 V	2.0	11.5	ns	
			140		IN	IN												"	"	"	"	
			142																"	"	"	"
			143																"	"	"	"
			144																"	"	"	"
			145																"	"	"	"
			146																"	"	"	"
	TpLH5		147																	"	"	"
			148																"	"	"	"
			149		IN	IN													"	"	"	"
			150																"	"	"	"
			151																"	"	"	"
			152																"	"	"	"
			153																"	"	"	"
			154																"	"	"	"
	TpHL6		155																	"	"	"
			156																"	"	"	"
			157		IN	IN													"	"	"	"
			158																"	"	"	"
			159																"	"	"	"
			160																"	"	"	"
			161																"	"	"	"
			162																"	"	"	"
	TpLH6		163																	"	"	"
			164																"	"	"	"
			165																"	"	"	"
			166		IN	IN													"	"	"	"
			167																"	"	"	"
			168																"	"	"	"
			169																"	"	"	"
			170																"	"	"	"
11																						

11 Same tests, terminal conditions, and limits as for subgroup 10, except $T_C = -55^\circ C$.

1/ For circuit B, $I_{OS(max)} = -1.10 \text{ mA}$.

2/ $A = 2.4 \text{ V}; B = 0.4 \text{ V}$.

3/ $H \geq 1.5 \text{ V}; L \leq 1.5 \text{ V}$.

4/ Only a summary of attributes is required.

5/ Case 2 pins not designated are NC.

TABLE III. Group A inspection for device type 02.
Terminal conditions (pins not designated may be R ≥ 22.0 V, or L ≤ 0.6 V, or open)

Subgroup	Symbol	MIL-Cases (STD-883 X2, 57) one-node	Test		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Measured terminal	Min	Max	Test limits	
			No.	1 ₃																					
T _C = +25°C	V _{OH} V _{OL}	3006 3006	1	0.8 V	0.8 V																				
	V _{OL}	3007 3007	2	0.8 V	0.8 V																				
V _{IC}		5	6	-18 mA																					
		7	8		-18 mA																				
		9	10			-18 mA																			
		11	12				-18 mA																		
		13	14					-18 mA																	
		15	16						-18 mA																
I _{IL}	3039	17	18	0.5 V	0.5 V																				
	"	19	20	GND	GND																				
		21	22	GND	GND																				
		23	24	5.5 V	5.5 V																				
		25	26	GND	GND																				
		27	28	5.5 V	5.5 V																				
I _{IL}	3041	29	30	2.7 V	2.7 V																				
	"	31	32	5.5 V	5.5 V																				
		33	34	5.5 V	5.5 V																				
		35	36	GND	GND																				
		37	38	5.5 V	5.5 V																				
		39	40	GND	GND																				
I _{IL}	"	41	42	5.5 V	5.5 V																				
	"	43	44	5.5 V	5.5 V																				
		45	46	5.5 V	5.5 V																				
		47	48	GND	GND																				
		49	50	5.5 V	5.5 V																				

See footnotes at end of device type 02.

TABLE III. Group A inspection for
Terminal conditions (pins not designated ma)

Subgroup	Symbol	Test no.	MIL-EF, SMD-833 X, 2.5V	Cases 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20	Measured terminal	Test limits		
						Min	Max	
1. $T_C = +23^\circ C$	V_{DH}	3016	1 2 3 4 5 6 7 8	2.0 V -1 mA	2.0 V -1 mA	0.8 V -1 mA	4.5 V 2.0 V 3Y 4Y	1Y 2Y 3Y 4Y
"	"	"	"	"	"	"	"	"
V_{OL}	3017	5 6 7 8	"	20 mA 20 mA 20 mA 20 mA	20 mA 20 mA 20 mA 20 mA	2.0 V "	0.5 V "	0.5 V "
V_{IC}	10	9 11 12 13 14 15 16 17 18	-18 mA -10 mA -10 mA -18 mA -18 mA -18 mA -18 mA -18 mA -18 mA	"	"	"	"	-1.2
"	"	"	"	"	"	"	"	"
I_{IL}	3009	19 20 21 22 23 24 25 26 27 28	5.5 V 5.5 V 5.5 V 5.5 V 5.5 V 5.5 V 5.5 V 5.5 V 5.5 V 5.5 V	0.5 V 0.5 V 0.5 V 0.5 V 0.5 V 0.5 V 0.5 V 0.5 V 0.5 V 0.5 V	GND GND GND GND GND GND GND GND GND GND	0.5 V 5.5 V GND GND GND GND GND GND GND GND	6 1A 1B 1C 1D 1E 1F 1G 1H 1I	-2.0 -2.0 -2.0 -2.0 -2.0 -2.0 -2.0 -2.0 -2.0 -2.0
"	"	"	"	"	"	"	"	"
I_{IH2}	3313	29 30 31 32 33 34 35 36 37 38	5.5 V 5.5 V 5.5 V 5.5 V 5.5 V 5.5 V 5.5 V 5.5 V 5.5 V 5.5 V	2.7 V 2.7 V 2.7 V 2.7 V 2.7 V 2.7 V 2.7 V 2.7 V 2.7 V 2.7 V	GND GND GND GND GND GND GND GND GND GND	2.7 V 5.5 V GND GND GND GND GND GND GND GND	6 1A 1B 1C 1D 1E 1F 1G 1H 1I	100 100 100 100 100 100 100 100 100 100
"	"	"	"	"	"	"	"	"
I_{O2}	3311 3312	49 50	5.5 V 5.5 V	5.5 V 5.5 V	GND GND	GND GND	1Y 2Y	-40 -40
"	"	"	"	"	"	"	"	"

See footnotes at end of device type U3.

TABLE III. Group A inspection for device type 03 - Continued.
Terminal conditions (pins not designated may be H \geq 2.0 V, or L \leq 0.8 V, or open)

Subgroup	Symbol	Test method	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Test limits
	SI0-883 (X,2,5)	Test no.	S	1A	1B	1Y	2A	2B	2Y	GND	3Y	3A	4Y	4B	4A	6	V _{CC}		
T _C = +25°C	tPHL3	3003 Fig. 7	91	92	93	94										IN	5.0 V	1Y 2Y 3Y 4Y	2.0 14 ns ns
	tpLH3	"	95	"	96	"	97	"	98	"						OUT	GND	2.7 V	0.0 T
T _C = +125°C	tPHL1	100	99	IN	GND	2.7 V	OUT	2.7 V	GND	2.7 V	OUT	2.7 V	GND	2.7 V	OUT	GND	2.7 V	0.0 T	
	tpLH1	"	101	"	102	"										OUT	2.7 V	0.0 T	
	tpHL2	"	103	"	104	"	105	"	106	"						OUT	2.7 V	0.0 T	
	tpHL2	"	107	"	108	"	109	"	110	"						OUT	2.7 V	0.0 T	
	tpLH2	"	111	"	112	"	113	"	114	"						OUT	2.7 V	0.0 T	
	tpHL3	"	115	"	116	"	117	"	118	"						OUT	2.7 V	0.0 T	
	tpLH3	"	119	"	120	"	121	"	122	"						OUT	2.7 V	0.0 T	

11 Same tests, terminal conditions, and limits as for subgroup 10, except T_C = -55°C.

1/ For circuit 3, I_{DS(max)} = -1.0 mA.

2/ A = 2.4 V; 3 = 0.4 V.

3/ A \geq 1.5 V; L \leq 1.5 V.

4/ Only a summary of attributes is required.

5/ Case 2 pins not designated are AC.

6/ For circuit 3, 0.1/-2 mA.

7/ For circuit 3, 0.1/-2 mA.

TABLE III. Group A inspection for device type 04,
Terminal conditions (pins not designated may be H ≥ 2.0 V, or L ≤ 0.8 V, or open)

Subgroup	Symbol	MIL-EF STD-883 X22.27	Cases												Test Limits			
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
T _C = +25°C	V _{OH}	3006	1	2	3	4	5	7	8	9	10	12	13	14	15	17	18	19
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"
	V _{OL}	3007	5	2.0 V	2.0 V	2.0 mA	2.0 V	2.0 mA	2.0 V	2.0 V	2.0 mA	2.0 V	2.0 V	2.0 V	2.0 V	4.5 V	4.5 V	4.5 V
		"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"
	V _{IC}		9	-18 mA	0.8 V	0.8 V	0.5 V											
		"	10	11	12	13	14	15	16	17	18	"	"	"	"	"	"	"
	I _{IL}	3009	19	5.5 V	0.5 V	5.5 V	0.5 V	5.5 V	5.5 V	-1.2 V								
		"	20	21	22	23	24	25	26	27	28	"	"	"	"	"	"	"
	I _{IH1}	3110	29	GND	2.7 V	2.7 V	2.7 V	2.7 V										
		"	31	32	33	34	35	36	37	38	"	"	"	"	"	"	"	"
	I _{IH2}	"	39	GND	5.5 V	5.5 V	5.5 V	5.5 V										
		"	40	41	42	43	44	45	46	47	48	"	"	"	"	"	"	"
	I _{OS}	3011	49	50								GND						

See footnotes at end of device type 04.

TABLE III. Group A inspection for device type 04 - Continued.
(Pins not designated may be H > 2.0 V, or L < 0.8 V, or open)

Subgroup	Symbol	Cases Alt- IE STD-883 T ₁ ,2 S ₁	Terminal conditions																Test limits				
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Measured terminal	Min	Max	Unit	
T _C = +25°C	tP _{LH3}	3003 F13 ₁ ₇ ₁	91 92 93 94	GND 2.7 V	GND OUT	2.7 V	GND JUT	IN GND	5.0 V	1V	2.0	14											
T _C = +125°C	tP _{LH1}	95 96 97 98	" " " "	2.7 V	GND JND	2.7 V	GND JUT	1V	2V	3V	4V	"											
	tP _{LH1}	99 101 102	" " "	GND 2.7 V	GND OUT	2.7 V	GND JUT	1V	2V	3V	4V	"											
	tP _{LH2}	103 104 105 106	" " " "	GND 2.7 V	GND OUT	2.7 V	GND JUT	1V	2V	3V	4V	"											
	tP _{LH2}	107 108 109 110	" " " "	GND IN	GND OUT	IN	GND JUT	GND IN	1V	2V	3V	4V	"										
	tP _{LH2}	111 112 113 114	" " " "	IN	GND OUT	IN	GND JUT	GND IN	1V	2V	3V	4V	"										
	tP _{LH3}	115 116 117 118	" " " "	2.7 V	GND OUT	2.7 V	GND JUT	GND IN	1V	2V	3V	4V	"										
	tP _{LH3}	119 120 121 122	" " " "	2.7 V	GND OUT	2.7 V	GND JUT	GND IN	1V	2V	3V	4V	"										

11 Same tests, terminal conditions, and limits as for subgroup 10, except T_C = -55°C.

1/¹ For circuit B, I_{Q3(max)} = -110 mA.

2/² A = 2.4 V; B = 0.4 V.

3/³ d ≥ 1.5 V; L ≤ 1.5 V.

4/⁴ Only a summary of attributes is required.

5/⁵ Case 2 pins not designated are NC.

6/⁶ For circuit B, 0.1/-4 mA.

7/⁷ Circuit B, 0.1/-2 mA.

TABLE III. Group A inspection for device type 05
 Terminal conditions (pins not designated may be H \geq 2.0 V, or L \leq 0.8 V, or open)

Symbol		Bases		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Test limits
Subgroup	MIL-STD-883 method	Test no.	Test no.	J3	J2	J1	J0	I	A	S	T	GND	C	A	J7	D6	J5	VCC	Unit	
$I_C = +25^\circ C$	V_{OL}	3007	1																	
		3007	2																	
V_{OH}		3006	3																	
		3006	4																	
I_{UFF1}		5																		
		6																		
I_{UFF2}		7																		
		8																		
I_{JS}		9																		
		10																		
I_{IH1}		11																		
		12																		
		13																		
		14																		
		15																		
		16																		
		17																		
		18																		
		19																		
		20																		
		21																		
		22																		
I_{IH2}		23																		
		24																		
		25																		
		26																		
		27																		
		28																		
		29																		
		30																		
		31																		
		32																		
		33																		
		34																		
I_{IL}		35																		
		36																		
		37																		
		38																		
		39																		
		40																		
		41																		
		42																		
		43																		
		44																		
		45																		
		46																		
I_{CC1}		3005	47																	

See footnotes at end of device type 05.

TABLE III. Group A inspection for device type 05 - Continued.
Terminal conditions (pins not designated may be H \geq 0.7 V, or L \leq 0.8 V, or open)

Subgroup	Symbol	Cases STD-883 IEC, X,25°	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Test limits				
			Test no.	03	02	01	00	Y	A	S/T	AD	C	3	A	S/T	AD	GND	GND	5.0 V	4	2.0	9.0	ns
			103	104	105														04	V _{CC}	Min	Max	Unit
$T_C = +25^\circ C$	t _{PHL4}	"	103	98	99	100	101	102	103	104	105												
		"	106	107	108	109	110	111	112	113	114	1N											
		"	115	116	117	118	119	120	121	122	123	1N											
	t _{P,L44}	"	114	115	116	117	118	119	120	121	122	1N											
	t _{LH}	"	122																				
	t _{ZL}	"	123																				
	t _{HZ}	"	124																				
	t _{LZ}	"	125																				
	t _{CH}	"	126																				
	t _{ZL}	"	127																				
	t _{HZ}	"	128																				
	t _{LZ}	"	129																				
$T_C = +145^\circ C$	t _{PHL1}	"	130	131	132																		
		"	133	134	135																		
	t _{PLA1}	"	131	2.7 V	2.7 V	2.7 V																	

See footnotes at end of device type 05.

TABLE III. Group A inspection for device type 05 - Continued.
Terminal conditions pins not designated may be H ≥ 2.0 V, or L ≤ 0.3 V, or open)

Subgroup	Symbol	Cases All- STD 883 method	Test limits																
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
	t_{PHL2}	136 137 138	2.7 V	2.7 V	"	"	"	"	"	"	"	"	"	"	"	5.0 V	"	2.0 ns	"
	t_{PHL2}	139 140 141	2.7 V	2.7 V	"	"	"	"	"	"	"	"	"	"	"	2.7 V	"	"	"
	t_{PLH3}	142 143 144 145 146 147 148 149	14	14	"	"	"	"	"	"	"	"	"	"	"	5.0 V	"	2.0 ns	"
	t_{PLH3}	150 151 152 153 154 155 156 157	"	"	"	"	"	"	"	"	"	"	"	"	"	2.7 V	"	"	"
	t_{PLH4}	158 159 160 161 162 163 164 165	14	14	"	"	"	"	"	"	"	"	"	"	"	2.7 V	"	"	"
	t_{PLH4}	166 167 168 169 170 171 172 173	"	"	"	"	"	"	"	"	"	"	"	"	"	2.7 V	"	"	"
	t_{ZL1}	174 175	"	"	"	"	"	"	"	"	"	"	"	"	"	2.7 V	"	25.5 ns	"
	t_{ZL2}	176	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	27.5 ns	"
	t_{ZL2}	177	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	24 ns	"
	t_{ZH3}	178	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	22 ns	"
	t_{ZH3}	179	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	25.5 ns	"

See footnotes at end of device type 05.

TABLE III. Group A inspection for device type DS - Continued.
 Terminal conditions (pins not designated may be H \geq 2.0 V, or L \leq 0.8 V, or open)

Subgroup	Symbol	MIL-STD-883 Test method	Cases				Test no.	J2	J1	J0	Y	A	S1	GND	C	S	A	J7	J6	D5	J4	V _{CC}	Measured		Test limits		
			1	2	3	4																	Min	Max			
T _C = +125°C	T _{L3}	Fig. 9	3003	179				J10	J1	J0	Y	A	S1	GND	C	S	A	J7	J6	D5	J4	V _{CC}	5.0 V	Y	2.0	[27.5 ns]	
	r _{H24}	"	180																					"	"	"	"
	r _{L24}	"	181					J10																"	"	"	"
11	Same tests, terminal conditions, and limits as for subgroup 10, except T _C = -55°C.																										

1/^U For circuit B, I_{DS(max)} = -110 mA.

2/^U A = 2.4 V; B = 0.4 V.

3/^U H \geq 1.5 V; L \leq 1.5 V.

4/^U Only a summary of attributes is required.

5/^U Case 2 pins not designated are NC.

MIL-M-38510/79C
Table III. Group A inspection for device type 06 - Continued.
Terminal conditions (pins not designated may be H \geq 2.0 V, or L \leq 0.8 V, or open)

Subgroup	Symbol	Cases 41L- 3383 X,2,77/ method	Test												Test limits			
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
$T_C = +25^\circ C$	V _{DH}	3306 " " " " "	2.0 V " " " " "	2.0 V " " " " "	-2 mA " " " " "	2.0 V " " " " "	-2 mA " " " " "	GND " " " " "	2V " " " " "	GND " " " " "	-2 mA " " " " "	2.0 V " " " " "	-2 mA " " " " "	0.8 V " " " " "	4.5 V " " " " "	1Y " " " " "	2.4 Y " " " " "	
$T_C = +25^\circ C$	V _{OL}	3307 " " " " "	3.8 V " " " " "	3.8 V " " " " "	20 mA " " " " "	0.8 V " " " " "	20 mA " " " " "	GND " " " " "	3V " " " " "	GND " " " " "	20 mA " " " " "	0.8 V " " " " "	20 mA " " " " "	0.8 V " " " " "	" " " " " " " "	" " " " " " " "	" " " " " " " "	
I_{DFF1}		9 13 11 12 " " "	GND " " " "	GND " " " "	2.7 V " " " "	3V " " " "	2.7 V " " " "	GND " " " "	2.7 V " " " "	GND " " " "	2.7 V " " " "	GND " " " "	GND " " " "	2.0 V " " " "	5.5 V " " " "	1Y " " " "	0.5 Y " " " "	
I_{DFF2}		13 14 15 16 " " "	5.5 V " " " "	5.5 V " " " "	0.5 V " " " "	5.5 V " " " "	0.5 V " " " "	GND " " " "	5.5 V " " " "	GND " " " "	5.5 V " " " "	GND " " " "	GND " " " "	2.0 V " " " "	5.5 V " " " "	1Y " " " "	50 μA " " " "	
I_{CCX}		17 18 19 20 " " "	5.5 V " " " "	5.5 V " " " "	5.5 V " " " "	5.5 V " " " "	5.5 V " " " "	GND " " " "	5.5 V " " " "	GND " " " "	5.5 V " " " "	GND " " " "	GND " " " "	0.5 V " " " "	5.5 V " " " "	1Y " " " "	-50 μA " " " "	
I_{ILO}		21 22 23 24 25 26 27 28 29 30 " " "	0.5 V " " " "	0.5 V " " " "	0.5 V " " " "	0.5 V " " " "	0.5 V " " " "	GND " " " "	0.5 V " " " "	GND " " " "	0.5 V " " " "	GND " " " "	GND " " " "	0.5 V " " " "	5.5 V " " " "	1Y " " " "	250 μA " " " "	
I_{TAA}		31 32 33 34 35 36 37 38 39 40 " " "	2.7 V " " " "	5.5 V " " " "	2.7 V " " " "	2.7 V " " " "	2.7 V " " " "	GND " " " "	2.7 V " " " "	GND " " " "	2.7 V " " " "	GND " " " "	GND " " " "	2.7 V " " " "	2.7 V " " " "	1.0 mA " " " "	100 μA " " " "	
I_{TAD}		41 42 43 44 45 46 47 48 49 50 " " "	5.5 V " " " "	5.5 V " " " "	5.5 V " " " "	5.5 V " " " "	5.5 V " " " "	GND " " " "	5.5 V " " " "	GND " " " "	5.5 V " " " "	GND " " " "	GND " " " "	5.5 V " " " "	5.5 V " " " "	1.0 mA " " " "	50 μA " " " "	

See footnotes at end of device type 06.

TABLE III. Group A inspection for device type 36 - Continued.
Terminal conditions (pins not designated may be H \geq 2.5 V, or L \leq 0.8 V, or open)

Subgroup	Symbol	Alt. E.F.	Cases	Test no.								Test limits								
				1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	Unit	
$T_C = +25^\circ C$	I _{DS}	STD-883 X,2,7/ ¹	2	3	4	5	7	8	9	10	12	13	14	15	17	18	19	20	MIL-M-38510/79C	
		"	5	52	53	53	53	53	54	54										
	I _{CCH}	3005	55	"	2N0	5.5 V	GND	5.5 V	GND	GND										
	I _{SSL}	"	56	GND	GND	GND				GND										
	I _{CCO}	"	57	2N0	2N0	2N0	2N0	2N0	2N0											
	V _{IC}		58	-18 mA	-13 mA															
			59	60	61	62	63	64	65	66	67									
2								Same tests, terminal conditions, and limits as for subgroup 1, except $T_C = 125^\circ C$ and V _{IC} tests are omitted. V _{IL} = 0.7 V, V _{OL(max)} = 0.45 V.												
3								Same tests, terminal conditions, and limits as for subgroup 1, except $T_C = -55^\circ C$ and V _{IC} tests are omitted.												
7								Same tests, terminal conditions, and limits as for subgroup 1, except $T_C = +125^\circ C$ and $-55^\circ C$. See 2.												
$T_C = -25^\circ C$ Table test:								Same tests, terminal conditions, and limits as for subgroup 1, except $T_C = +125^\circ C$ and $-55^\circ C$. See 2.												
Same tests, terminal conditions, and limits as for subgroup 7, except $T_C = +125^\circ C$ and $-55^\circ C$. See footnotes at end of device type 36.								Same tests, terminal conditions, and limits as for subgroup 7, except $T_C = +125^\circ C$ and $-55^\circ C$. See footnotes at end of device type 36.												

Table III. Group A inspection for device type 06 - Continued.
Terminal conditions (pins not designated may be H ≥ 2.0 V, or L ≤ 0.8 V, or open)

Test no.	Cases E,F, X,27/ 1	MIL- STD-883 method	S	1A	1B	1Y	2A	2B	2Y	GND	3Y	3B	3A	4Y	4B	4A	DE	V _{CC}	Test limits					
																			terminal	Min	Max	Unit		
$T_C = +25^{\circ}\text{C}$	t _{PHL1}	3003 Fig. 10	84	1A	GND	2.7 V	JUT	GND	2.7 V	JUT	GND	2.7 V	JUT	2.7 V	GND	JUT	2.7 V	GND	5.0 V	1Y	2.0	17	ns	
	"	85 86	87	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	2Y	"	"	"	
	t _{PLH1}	"	88	1A	GND	2.7 V	JUT	GND	2.7 V	JUT	GND	2.7 V	JUT	2.7 V	GND	JUT	2.7 V	GND	"	1Y	"	"	"	
	"	89 90	91	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	2Y	"	"	"	"	
	t _{PLL2}	"	92	GND	IN	GND	JUT	IN	GND	JUT	IN	GND	JUT	IN	GND	JUT	IN	GND	1A	"	4Y	"	"	
	"	93 94	95	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	1Y	"	8.0	"	"
	t _{PLL42}	"	96	"	IN	GND	JUT	IN	GND	JUT	IN	GND	JUT	IN	GND	JUT	IN	GND	1A	"	1Y	"	"	"
	"	97 98	99	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	2Y	"	3Y	"	"
	t _{ZL1}	"	100	2.7 V	2.7 V	JUT	2.7 V	JUT	2.7 V	JUT	GND	2.7 V	JUT	2.7 V	GND	JUT	2.7 V	GND	"	1Y	"	9.0	"	"
	"	101 102	103	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	2Y	"	3Y	"	"	"
	t _{ZL2}	"	104	GND	GND	JUT	GND	JUT	GND	JUT	GND	2.7 V	JUT	2.7 V	GND	JUT	2.7 V	GND	"	1Y	"	21.5	"	"
	"	105 106	107	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	2Y	"	3Y	"	"	"
	t _{H2-5/}	"	108	2.7 V	2.7 V	JUT	2.7 V	JUT	2.7 V	JUT	GND	2.7 V	JUT	2.7 V	GND	JUT	2.7 V	GND	"	1Y	"	23	"	"
	"	109 110	111	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	2Y	"	3Y	"	"	"
	t _{L2}	"	112	GND	JUT	GND	JUT	GND	JUT	GND	JUT	GND	JUT	GND	JUT	GND	JUT	GND	"	1Y	"	11.5	"	"
	"	113 114	115	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	2Y	"	3Y	"	"	"
	t _{PLH1}	"	116	1A	GND	2.7 V	JUT	GND	2.7 V	JUT	GND	2.7 V	JUT	2.7 V	GND	JUT	2.7 V	GND	GND	1Y	"	22	"	"
	"	117 118	119	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	2Y	"	3Y	"	"	"
	t _{PLL1}	"	120	GND	2.7 V	JUT	GND	2.7 V	JUT	GND	2.7 V	JUT	2.7 V	GND	JUT	2.7 V	GND	GND	1Y	"	2Y	"	"	"
	"	121 122	123	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	3Y	"	4Y	"	"	"

See footnotes at end of device type 06.

TABLE III. Group A inspection for device type 06 - Continued.
Terminal conditions (pins not designated may be $R \geq 2.0$ V, or $L \leq 0.8$ V, or open)

Symbol	Cases	Test limits													
		1	2	3	4	5	6	7	8	9	10	11	12	13	14
t_{L-} method	t_{L-} t_{L-}	IF, F, $X, 2.7$	2	3	4	5	7	8	9	10	12	13	14	15	16
test no.	S	IA	13	1Y	2A	2B	2Y	GND	3Y	3A	4Y	4B	4A	OE	V _{CC}
t_{D-} $T_C = +125^\circ C$	t_{D-} t_{D-}	3003	124	GND	IN	GND	JUT	GND	OUT	GND	IN	JUT	GND	5.0 V	IY 2Y 3Y 4Y
		10	123	*											
		126	*												
		127	*												
t_{PdH2}	*	128	*	1A	GND	JUT	IN	GND	OUT	GND	IN	JUT	GND	IN	IY 2Y 3Y 4Y
	*	129	*												
	*	130	*												
	*	131	*												
t_{Zd}	*	132	2.7 V	2.7 V	OUT	2.7 V	OUT	*	0JT	2.7 V	OUT	2.7 V	OUT	IY 2Y 3Y 4Y	28
	*	133	*												
	*	134	*												
	*	135	*												
t_{ZL}	*	136	2.7 V	2.7 V	OUT	2.7 V	OUT	*	0JT	2.7 V	OUT	2.7 V	OUT	IY 2Y 3Y 4Y	30
	*	137	*												
	*	138	*												
	*	139	*												
$t_{HL} \leq$	*	140	2.7 V	2.7 V	OUT	2.7 V	OUT	*	0JT	2.7 V	OUT	2.7 V	OUT	GND	IY 2Y 3Y 4Y
	*	141	*												
	*	142	*												
	*	143	*												
t_{LZ}	*	144	*	GND	OUT	GND	OUT	*	0JT	2.7 V	OUT	2.7 V	OUT	GND	IY 2Y 3Y 4Y
	*	145	*												
	*	146	*												
	*	147	*												

11 Same tests, terminal conditions, and limits as for subgroup 10, except $T_C = -35^\circ C$.

1/ For circuit B, $I_{DS(\text{max})} = -110 \text{ mA}$.

2/ $A = 2.4 \text{ V}, B = 0.4 \text{ V}$.

3/ $H \geq 1.5 \text{ V}, L \leq 1.5 \text{ V}$.

4/ Only a summary of attributes is required.

5/ t_{dZ} maximum limit for circuit C is 22 ns.

6/ t_{dZ} maximum limit for circuit C is 24 ns.

7/ Case 2 pins not designated are dC.

TABLE III. Group A inspection for device type 07.
Terminal conditions (pins not designated may be H ≥ 2.0 V, or L ≤ 0.8 V, or open)

Subgroup	Symbol	MIL-STD-883 method	Cases test no.	Test												Measured		Test limits			
				1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Unit	
$T_C = +25^\circ C$	V_{DH}	3006	1 " " "	2.0 V	0.8 V	-2.0 mA	0.8 V	-2.0 mA	GND	3Y	3B	3A	4Y	4B	4A	3E	VCC	0.8 V	4.5 V	1Y 2Y 3Y 4Y	
		"	2 " " "	2.0 V	0.8 V	-2.0 mA	0.8 V	-2.0 mA	"	"	"	"	"	"	"	"	"	"	2.4 V	"	
	V_0	3007	5 " " "	0.8 V	2.0 V	20 mA	2.0 V	20 mA	"	"	"	"	"	"	"	"	"	"	0.5 V	"	
		"	6 " " "	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	2.0 V	5.5 V	
I_{OFF1}		9 10 11 12	GND " " "	5.5 V	2.7 V	5.5 V	2.7 V	5.5 V	"	"	"	"	"	"	"	"	"	"	2.0 V	5.5 V	
		"	11 " " "	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	1Y 2Y 3Y 4Y	50 μA	
	I_{OFF2}	13 14 15 16	5.5 V " " "	GND " " "	0.5 V	GND " " "	1Y 2Y 3Y 4Y	-50 μA													
		"	15 " " "	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	1Y 2Y 3Y 4Y	"	
I_{CCK}		17 18 19 20	5.5 V " " "	GND " " "	5.5 V	GND " " "	1Y 2Y 3Y 4Y	250 μA													
		"	19 " " "	"	"	"	"	"	"	"	"	"	"	"	"	"	"	"	1Y 2Y 3Y 4Y	"	
	I_{IL}	3009	21 " " "	0.5 V GND	0.5 V	S -2.0 V 0.5 V 1A 2A 3A 3B 3C 3D 4A	-2.0 μA														
		"	22 " " "	GND " " "	0.5 V	S -1.0 V 0.5 V 1A 2A 3A 3B 3C 3D 4A	-1.0 μA														
I_{IHD}		31 32 33 34 35 36 37 38 39 40	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	2.7 V GND	100 μA
		"	33 " " "	2.7 V GND	2.7 V GND	100 μA															
	I_{IH2}	41 42 43 44 45 46 47 48 49 50	"	5.5 V GND	5.5 V GND	1.0 μA															
		"	42 " " "	5.5 V GND	5.5 V GND	1.0 μA															

See footnotes at end of device type 07.

TABLE 111. Group A inspection for device type 07 - Continued.
Terminal conditions (pins not designated may be H ≥ 2.0 V, or L ≤ 0.8 V, or open)

		Cases										Test limits					
Subgroup	Symbol	MIL-S STC-83 method	1 EF X27	2 3	4	5	6	7	8	9	10	11	12	13	14	15	16
TC = +25°C	I _{DS}	3011 " " "	51 52 53 54	5.5 V	GND	GND	GND	GND	GND	GND	GND	GND	GND	5.5 V	-40 °C	-100 °C	
I _{CCH}	3005	55 " " "	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	" "	2Y	" "	
I _{CCL}	"	56 " " "	GND	5.5 V	GND	5.5 V	GND	5.5 V	GND	5.5 V	GND	5.5 V	GND	" "	V _{CC}	56 °C	
I _{CCO}	"	57 " " "	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	5.5 V	" "	V _{CC}	81 °C
V _{IC}	"	58 59 60 61 62 63 64 65 66 67	-18 mA -18 mA -18 mA -18 mA -18 mA -18 mA -18 mA -18 mA -18 mA -18 mA	H	H	H	H	H	H	H	H	H	H	4.5 V	S	-1.2 Y	
2 Same tests, terminal conditions, and limits as for subgroup 1, except TC = +125°C and VIC tests are omitted. V _{IL} = 0.7 V, V _{OL(max)} = 0.45 V.																	
3 Same tests, terminal conditions, and limits as for subgroup 1, except TC = -55°C and VIC tests are omitted.																	
7 4/ ₂	Truth Table test	3014 " " "	68 69 70 71 72 73 74 75 76 77 78 79 80 81 82 83	A 2/ ₂ A 2/ ₂ A 3 A 3	H H A A L A H A A L A A A A A L	GND	GND	GND	GND	GND	GND	GND	B 2/ ₂ B 2/ ₂ A A L A A A H A A A A A B	4.5 V	See J ₂		
4/ Same tests, terminal conditions, and limits as for subgroup 7, except TC = +125°C and -55°C.																	
T _C = +25°C	tPHL1 tPLH1	3003 " " "	84 85 87	I _D " " "	GND	2.7 V	0UT	tND	2.7 V	0UT	tND	2.7 V	0UT	GND	5.0 V	IY	2.0 ns
T _C = +25°C	tPLH1	" " "	88 89 90 91	" "	GND	2.7 V	0UT	tND	2.7 V	0UT	tND	2.7 V	0UT	GND	5.0 V	2Y	" "

See footnotes at end of device type 07.

TABLE III. Group A inspection for device type 07 - Continued.
Terminal conditions (pins not designated may be H \geq 2.0 V, or L \leq 0.8 V, or open)

Subgroup	Symbol	MIL-STD-883 E.F. method	Cases	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Test limits		
			STO-883 X,2,77	2	3	4	5	7	8	9	10	12	13	14	15	17	18	19	20	Measured terminal	Min	Max
T _C = +25°C	t _{PHL2}	3003 F13; 11	92 93 94 95	GND IN GND OUT	1A 1Y	2A 2Y	2B 2Y	GND JUT	GND OUT	GND IN	GND OUT	GND IN	GND OUT	GND IN	GND OUT	GND IN	GND OUT	GND IN	5.0 V GND	2.0 V 2Y 3Y 4Y	8.0 ns	
	t _{PLH2}	"	96 97 98 99	" IN GND OUT	" 1A GND JUT	" 2A GND JUT	" 2B GND JUT	" GND OUT	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND	" IN	" 2Y 3Y 4Y	" 2Y 3Y 4Y	
	t _{ZH}	"	100 101 102 103	2.7 V GND OUT	" 1A GND JUT	" 2A GND JUT	" 2B GND JUT	" GND OUT	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND	" IN	" 2Y 3Y 4Y	" 2Y 3Y 4Y	
	t _{ZL}	"	104 105 106 107	GND 2.7 V OUT	" 1A GND JUT	" 2A GND JUT	" 2B GND JUT	" GND OUT	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND	" IN	" 2Y 3Y 4Y	" 2Y 3Y 4Y	
	t _{HZ}	<u>5/</u>	108 109 110 111	2.7 V GND OUT	" 1A GND JUT	" 2A GND JUT	" 2B GND JUT	" GND OUT	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND	" IN	" 2Y 3Y 4Y	" 2Y 3Y 4Y	
	t _{LZ}	"	112 113 114 115	GND 2.7 V OUT	" 1A GND JUT	" 2A GND JUT	" 2B GND JUT	" GND OUT	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND	" IN	" 2Y 3Y 4Y	" 2Y 3Y 4Y	
T _C = +125°C	t _{PHL1}	"	116 117 118 119	IN GND 2.7 V OUT	" 1A GND JUT	" 2A GND JUT	" 2B GND JUT	" GND OUT	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND	" IN	" 2Y 3Y 4Y	" 2Y 3Y 4Y	
	t _{PLH1}	"	120 121 122 123	" GND 2.7 V OUT	" 1A GND JUT	" 2A GND JUT	" 2B GND JUT	" GND OUT	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND	" IN	" 2Y 3Y 4Y	" 2Y 3Y 4Y	
	t _{PHL2}	"	124 125 126 127	GND IN GND OUT	" 1A GND JUT	" 2A GND JUT	" 2B GND JUT	" GND OUT	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND	" IN	" 2Y 3Y 4Y	" 2Y 3Y 4Y	
	t _{PLH2}	"	128 129 130 131	" IN GND OUT	" 1A GND JUT	" 2A GND JUT	" 2B GND JUT	" GND OUT	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND	" IN	" 2Y 3Y 4Y	" 2Y 3Y 4Y	
	t _{ZH}	"	132 133 134 135	2.7 V GND OUT	" 1A GND JUT	" 2A GND JUT	" 2B GND JUT	" GND OUT	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND IN	" OUT	" GND	" IN	" 2Y 3Y 4Y	" 2Y 3Y 4Y	

See footnote at end of device type 07.

TABLE III. Group A inspection for device type 07 - Continued.
Terminal conditions (pins not designated may be $R \geq 2.0 \text{ V}$, or $L \leq 0.8 \text{ V}$, or open)

Subgroup	Symbol	MIL-STD-883 IEF, X,2 //	Cases												Test limits							
			1	2	3	4	5	6	7	8	9	10	12	13	14	15	16	Measured terminal	Min	Max	Unit	
$T_C = +125^\circ\text{C}$	t_{ZL}	3003 Fig. 11	136 137 138 139	GND 2.7 V GND 2.7 V	OUT 2.7 V	JUT 2.7 V	GND 2.7 V	JUT 2.7 V	IN " "	1Y 2Y 3Y 4Y	2.0 " "	30 " "	ns									
	$t_{HZ} \delta /$	"	140 141 142 143	2.7 V " " " " " "	SND OUT	JUT 2.7 V	" "	" "	1Y 2Y 3Y 4Y	" "	" "	" "										
	t_{LZ}	"	144 145 146 147	GND 2.7 V GND 2.7 V	OUT 2.7 V	JUT 2.7 V	GND 2.7 V	JUT 2.7 V	" "	" "	1Y 2Y 3Y 4Y	" "	" "	" "								
11	Same tests, terminal conditions, and limits as for subgroup 10, except $T_C = -55^\circ\text{C}$.																					

1/ For circuit B, $V_{DS(\text{max})} = -110 \text{ mV}$.

2/ $A = 2.4 \text{ V}; B = 0.4 \text{ V}$.

3/ $A \geq 1.5 \text{ V}; B \leq 1.5 \text{ V}$.

4/ Only a summary of attributes is required.

5/ t_{HZ} maximum limit for circuit C is 22 ns.

6/ t_{HZ} maximum limit for circuit C is 24 ns.

7/ Base 2 pins not designated are AC.

TABLE III. Group A inspection for device type 08 - Continued.
(pins not designated may be $H \geq 2.0\text{ V}$, or $L \leq 0.8\text{ V}$, or open)

Subgroup	Symbol	ML- [E, F] STD-383 [X, Z, S]	Cases	1	2	3	4	5	6	7	8	9	10	12	13	14	15	16	Test limits	
	Symbol	ML- [E, F] STD-383 [X, Z, S]	no.	1a	B	IC3	IC2	IC1	100	1Y	GND	2Y	200	2C1	2C2	2C3	A	2G	V _{CC}	Measured terminal
$T_C = +25^\circ\text{C}$	t_{PLH2}	3003 R ₁₃ , 12	91 92 93 94	GND GND IN IN	GND GND IN IN	SND	2.7V	OUT	GND	"	OUT	2.7V	SND	GND	GND	GND	5.0V	1Y	2.0	
	t_{ZH}	"	95 96	1Y GND	"	"	"	"	"	"	"	"	"	"	"	"	"	1Y	1Y	ns
	t_{ZL}	"	97 98	" "	"	"	"	"	"	"	"	"	"	"	"	"	"	2Y	2Y	"
	t_{HZ}	"	99 100	" "	"	"	"	"	"	"	"	"	"	"	"	"	"	1Y	1Y	"
	t_{LZ}	"	101 102	" "	"	"	"	"	"	"	"	"	"	"	"	"	"	2Y	2Y	"
i,j																				

i,j Same tests and terminal conditions as subgroup 9, with limits as follows: $t_{PHL1} = 14.5\text{ ns}$, $t_{PLH1} = 14.5\text{ ns}$, $t_{PLH2} = 26\text{ ns}$, $t_{PHL2} = 26\text{ ns}$, $t_{ZH} = 30\text{ ns}$, $t_{ZL} = 31\text{ ns}$, $T_C = +125^\circ\text{C}$, $t_{HZ} = 13\text{ ns}$, $t_{LZ} = 20\text{ ns}$.

11 Same tests, terminal conditions, and limits as for subgroup 10, except $T_C = -55^\circ\text{C}$.

1/ $A = 2.4\text{ V}$; $B = 0.4\text{ V}$.

2/ $d \geq 1.5\text{ V}$; $L \leq 1.5\text{ V}$.

3/ Only a summary of attributes is required.

4/ For circuit d, $I_{DS(\max)} = -110\text{ mA}$.

5/ Case 2 pins not designated are NC.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-M-38510 and methods 5005 and 5007, as applicable, of MIL-STD-883, except as modified herein.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on device type 01 prior to qualification and quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test (method 1015 of MIL-STD-883).

(1) Test condition D, using the circuit shown on figure 3, or equivalent.

(2) $T_A = +125^\circ\text{C}$ minimum.

b. Interim and final electrical test parameters shall be as specified in table II, except interim electrical parameters test prior to burn-in is optional at the discretion of the manufacturer.

c. The percent defective allowable (PDA) shall be as specified in MIL-M-38510.

4.3 Qualification inspection. Qualification inspection shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, and D inspections (see 4.4.1 through 4.4.4).

4.4 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, and D inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection. Group A inspection shall be in accordance with table I of method 5005 of MIL-STD-883 and as follows:

a. Electrical tests requirements shall be as specified in table II.

b. Subgroups 4, 5, and 6 of table I of method 5005 of MIL-STD-883 shall be omitted.

4.4.2 Group B inspection. Group B inspection shall be in accordance with table II of method 5005 of MIL-STD-883. Electrical test requirements shall be as specified in table II herein.

4.4.3 Group C inspection. Group C inspection shall be in accordance with table III of method 5005 of MIL-STD-883 and as follows:

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test (method 1005 of MIL-STD-883) conditions:

(1) Test condition D using the circuit shown on figure 3, or equivalent.

(2) $T_A = +125^\circ\text{C}$, minimum.

(3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.4 Group D inspection. Group D inspection shall be in accordance with table IV of method 5005 of MIL-STD-883. End-point electrical parameters shall be as specified in table II herein.

4.5 Methods of inspection. Methods of inspection shall be specified as follows.

4.5.1 Voltage and current. All voltages given are referenced to the microcircuit ground terminal. Currents given are conventional and positive when flowing into the referenced terminal.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this specification are intended for original equipment design applications and logistic support of existing equipment.

6.2 Ordering data. The acquisition document should specify the following:

- a. Complete part number (see 1.2).
- b. Requirements for delivery of one copy of the quality conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.
- c. Requirements for certificate of compliance, if applicable.
- d. Requirements for notification of change of product or process to the contracting activity in addition to notification to the qualifying activity, if applicable.
- e. Requirements for failure analysis (including required test condition of method 5005 of MIL-STD-883), corrective action and reporting of results, if applicable.
- f. Requirements for product assurance options.
- g. Requirements for special carriers, lead lengths, or lead forming. If applicable, these requirements shall not affect the part number. Unless otherwise specified, these requirements shall not apply to direct purchase by or direct shipment to the Government.
- h. Requirements for "JAN" marking.

6.3 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-M-38510, MIL-STD-1331, and as follows:

GND	- - - - -	Ground zero voltage potential.
I _{IN}	- - - - -	Current flowing into an input terminal.
V _{IN}	- - - - -	Voltage level at an input terminal.
t _{ZH}	- - - - -	Output enable time (of a three-state output) to high level. The time between the specified reference points on the input and output voltage waveforms with the three-state output changing from a high-impedance (off) state to the defined high level.
t _{ZL}	- - - - -	Output enable time (of a three-state output) to low level. The time between the specified reference points on the input and output voltage waveforms with the three-state output changing from a high-impedance (off) state to the defined low level.

t_{HZ}	Output disable time (of a three-state output) from high level. The time between the specified reference points on the input and output voltage waveforms with the three-state output changing from the defined high level-impedance (off) state.
t_{LZ}	Output disable time (of a three-state output) from low level. The time between the specified reference points on the input and output voltage waveforms with the three-state output changing from the defined low level to a high-impedance (off) state.

6.4 Logistic support. Lead materials and finishes (see 3.3) are interchangeable. Unless otherwise specified, microcircuits acquired for Government logistic support will be acquired to device class B (see 1.2.2), lead material and finish C (see 3.3). Longer length leads and lead forming shall not affect the part number.

6.5 Substitutability. The cross-reference information below is presented for the convenience of users. Microcircuits covered by this specification will functionally replace the listed generic-industry type. Generic-industry microcircuit types may not have equivalent operational performance characteristics across military temperature ranges or reliability factors equivalent to MIL-M-38510 device types and may have slight physical variations in relation to case size. The presence of this information shall not be deemed as permitting substitution of generic-industry types for MIL-M-38510 types or as a waiver of any of the provisions of MIL-M-38510.

<u>Military device type</u>	<u>Generic-industry type</u>
01	54S151
02	54S153
03	54S157
04	54S158
05	54S251
06	54S257
07	54S258
08	54S253

6.6 Manufacturers' designation. Manufacturers' circuits included in this specification are designated with an "X" as shown in table IV herein.

TABLE IV. Manufacturers' designations.

Device type	Commercial type	Circuits				
		A Texas Instruments	B Signetics Corp.	C Advanced Micro Devices Inc.	D Fairchild Semiconductor	E National Semiconductor
01	54S151	X	X	X	X	X
02	54S153	X	X	X	X	X
03	54S157	X	X	X	X	X
04	54S158	X	X	X	X	X
05	54S251	X		X	X	
06	54S257	X		X	X	
07	54S258	X	X	X	X	
08	54S253			X	X	

6.7 Changes from previous issue. Asterisks are not used in this revision to identify changes with respect to the previous issue, due to the extensiveness of the changes.

Custodians:

Army - ER
Navy - EC
Air Force - 17

Review activities:

Army - AR, MI
Navy - OS, SH, TD
Air Force - 11, 19, 85, 99
DLA - ES

User activities:

Army - SM
Navy - AS, CG, MC

Preparing activity:
Air Force - 17

Agent:
DLA - ES

(Project 5962-1047)